

CPC COOPERATIVE PATENT CLASSIFICATION

H ELECTRICITY

(NOTE omitted)

H05 ELECTRIC TECHNIQUES NOT OTHERWISE PROVIDED FOR

H05K PRINTED CIRCUITS; CASINGS OR CONSTRUCTIONAL DETAILS OF ELECTRIC APPARATUS; MANUFACTURE OF ASSEMBLAGES OF ELECTRICAL COMPONENTS

NOTES

1. This subclass covers:
 - combinations of a radio or television receiver with apparatus having a different main function;
 - printed circuits structurally associated with non-printed electric components.
2. In this subclass, the following expression is used with the meaning indicated:
 - "printed circuits" covers all kinds of mechanical constructions of circuits that consist of an insulating base or support carrying the conductor and are combined structurally with the conductor throughout their length, especially in a two-dimensional plane, the conductors of which are secured to the base in a non-dismountable manner, and also covers the processes or apparatus for manufacturing such constructions, e.g. forming the circuit by mechanical or chemical treatment of a conductive foil, paste, or film on an insulating support.

WARNING

In this subclass non-limiting references (in the sense of paragraph 39 of the Guide to the IPC) may still be displayed in the scheme.

1/00	Printed circuits	1/0221	{Coaxially shielded signal lines comprising a continuous shielding layer partially or wholly surrounding the signal lines}
1/02	. Details			
1/0201	. . {Thermal arrangements, e.g. for cooling, heating or preventing overheating}			
1/0203	. . . {Cooling of mounted components (H05K 1/0272 takes precedence)}	1/0222	{for shielding around a single via or around a group of vias, e.g. coaxial vias or vias surrounded by a grounded via fence}
1/0204 {using means for thermal conduction connection in the thickness direction of the substrate (H05K 1/0207 takes precedence)}	1/0224	{Patterned shielding planes, ground planes or power planes (H05K 1/0253 takes precedence)}
1/0206 {by printed thermal vias}			
1/0207 {using internal conductor planes parallel to the surface for thermal conduction, e.g. power planes}	1/0225	{Single or multiple openings in a shielding, ground or power plane (H05K 1/0227 takes precedence)}
1/0209 {External configuration of printed circuit board adapted for heat dissipation, e.g. lay-out of conductors, coatings}	1/0227	{Split or nearly split shielding or ground planes}
1/021 {Components thermally connected to metal substrates or heat-sinks by insert mounting}	1/0228	{Compensation of cross-talk by a mutually correlated lay-out of printed circuit traces, e.g. for compensation of cross-talk in mounted connectors (balanced signal pairs H05K 1/0245)}
1/0212	. . . {Printed circuits or mounted components having integral heating means}			
1/0213	. . {Electrical arrangements not otherwise provided for}	1/023	{using auxiliary mounted passive components or auxiliary substances (printed passive components H05K 1/16)}
1/0215	. . . {Grounding of printed circuits by connection to external grounding means}	1/0231	{Capacitors or dielectric substances}
1/0216	. . . {Reduction of cross-talk, noise or electromagnetic interference (grounding H05K 1/0215)}	1/0233	{Filters, inductors or a magnetic substance}
1/0218 {by printed shielding conductors, ground planes or power plane (H05K 1/0236 takes precedence)}	1/0234	{Resistors or by disposing resistive or lossy substances in or near power planes (H05K 1/0246 takes precedence)}
1/0219 {Printed shielding conductors for shielding around or between signal conductors, e.g. coplanar or coaxial printed shielding conductors}	1/0236	{Electromagnetic band-gap structures}
		1/0237	{High frequency adaptations (H05K 1/0216 takes precedence)}
		1/0239	{Signal transmission by AC coupling}

- 1/024 {Dielectric details, e.g. changing the dielectric material around a transmission line}
- 1/0242 {Structural details of individual signal conductors, e.g. related to the skin effect}
- 1/0243 {Printed circuits associated with mounted high frequency components}
- 1/0245 {Lay-out of balanced signal pairs, e.g. differential lines or twisted lines}
- 1/0246 {Termination of transmission lines}
- 1/0248 {Skew reduction or using delay lines}
- 1/025 {Impedance arrangements, e.g. impedance matching, reduction of parasitic impedance ([H05K 1/024](#) and [H05K 1/0243](#) take precedence; for semiconductor devices [H01L 23/66](#))}
- 1/0251 {related to vias or transitions between vias and transmission lines}
- 1/0253 {Impedance adaptations of transmission lines by special lay-out of power planes, e.g. providing openings ([H05K 1/0251](#) takes precedence)}
- 1/0254 . . . {High voltage adaptations; Electrical insulation details; Overvoltage or electrostatic discharge protection ([electrostatic discharge protection for electric apparatus in general H05K 9/0067](#), [H05K 9/0079](#)); Arrangements for regulating voltages or for using plural voltages}
- 1/0256 {Electrical insulation details, e.g. around high voltage areas}
- 1/0257 {Overvoltage protection}
- 1/0259 {Electrostatic discharge [ESD] protection}
- 1/026 {Spark gaps}
- 1/0262 {Arrangements for regulating voltages or for using plural voltages}
- 1/0263 . . . {High current adaptations, e.g. printed high current conductors or using auxiliary non-printed means; Fine and coarse circuit patterns on one circuit board ([H05K 1/0293](#) takes precedence)}
- 1/0265 {characterized by the lay-out of or details of the printed conductors, e.g. reinforced conductors, redundant conductors, conductors having different cross-sections}
- 1/0266 . . {Marks, test patterns or identification means}
- 1/0268 . . . {for electrical inspection or testing}
- 1/0269 . . . {for visual or optical inspection}
- 1/0271 . . {Arrangements for reducing stress or warp in rigid printed circuit boards, e.g. caused by loads, vibrations or differences in thermal expansion}
- 1/0272 . . {Adaptations for fluid transport, e.g. channels, holes}
- 1/0274 . . {Optical details, e.g. printed circuits comprising integral optical means ([H05K 1/0269](#) takes precedence; [coupling light guides with optoelectronic components G02B 6/42](#))}
- 1/0275 . . {Security details, e.g. tampering prevention or detection}
- 1/0277 . . {Bendability or stretchability details ([H05K 1/038](#), [H05K 3/4691](#) take precedence)}
- 1/0278 . . . {Rigid circuit boards or rigid supports of circuit boards locally made bendable, e.g. by removal or replacement of material}
- 1/028 {Bending or folding regions of flexible printed circuits ([H05K 1/0283](#) takes precedence)}
- 1/0281 {Reinforcement details thereof}
- 1/0283 {Stretchable printed circuits}
- 1/0284 . . {Details of three-dimensional rigid printed circuit boards ([H05K 1/119](#) takes precedence; [shaping of the substrate H05K 3/0014](#))}
- 1/0286 . . {Programmable, customizable or modifiable circuits ([by programmable non-printed jumper connections H05K 3/222](#))}
- 1/0287 . . . {having an universal lay-out, e.g. pad or land grid patterns or mesh patterns}
- 1/0289 {having a matrix lay-out, i.e. having selectively interconnectable sets of X-conductors and Y-conductors in different planes}
- 1/029 . . . {having a programmable lay-out, i.e. adapted for choosing between a few possibilities}
- 1/0292 . . . {having a modifiable lay-out, i.e. adapted for engineering changes or repair ([H05K 1/0293](#) takes precedence)}
- 1/0293 . . . {Individual printed conductors which are adapted for modification, e.g. fusable or breakable conductors, printed switches}
- 1/0295 . . . {adapted for choosing between different types or different locations of mounted components}
- 1/0296 . . {Conductive pattern lay-out details not covered by sub groups [H05K 1/02](#) - [H05K 1/0295](#) ([H05K 1/11](#) takes precedence; [lay-out adapted to mounted component configuration H05K 1/18](#))}
- 1/0298 . . . {Multilayer circuits}
- 1/03 . . . Use of materials for the substrate
- 1/0306 . . . {Inorganic insulating substrates, e.g. ceramic, glass}
- 1/0313 . . . {Organic insulating material}
- 1/032 {consisting of one material}
- NOTE**
- {In this group, in the absence of an indication to the contrary, a material is classified in the last appropriate place.}
- 1/0326 {containing O}
- 1/0333 {containing S}
- 1/034 {containing halogen}
- 1/0346 {containing N}
- 1/0353 {consisting of two or more materials, e.g. two or more polymers, polymer + filler, + reinforcement}
- 1/036 {Multilayers with layers of different types}
- 1/0366 {reinforced, e.g. by fibres, fabrics ([H05K 1/036](#) takes precedence)}
- 1/0373 {containing additives, e.g. fillers ([H05K 1/036](#) takes precedence)}
- 1/038 . . . {Textiles (used as reinforcing materials for organic insulating substrates [H05K 1/0366](#))}
- 1/0386 . . . {Paper sheets (used as reinforcing materials for organic insulating substrates [H05K 1/0366](#))}
- 1/0393 . . . {Flexible materials ([H05K 1/038](#) takes precedence; specific organic compositions are classified in [H05K 1/0313](#) and subgroups)}
- 1/05 . . . Insulated {conductive substrates, e.g. insulated} metal substrate

- 1/053 {the metal substrate being covered by an inorganic insulating layer}
- 1/056 {the metal substrate being covered by an organic insulating layer}
- 1/09 . . Use of materials for the {conductive, e.g. } metallic pattern
- 1/092 {Dispersed materials, e.g. conductive pastes or inks}
- 1/095 {for polymer thick films, i.e. having a permanent organic polymeric binder}
- 1/097 {Inks comprising nanoparticles and specially adapted for being sintered at low temperature ([H05K 1/095 takes precedence](#))}
- 1/11 . . Printed elements for providing electric connections to or between printed circuits
- 1/111 {Pads for surface mounting, e.g. lay-out}
- 1/112 {directly combined with via connections}
- 1/113 {Via provided in pad; Pad over filled via}
- 1/114 {Pad being close to via, but not surrounding the via}
- 1/115 {Via connections; Lands around holes or via connections ([H05K 1/112 takes precedence](#))}
- 1/116 {Lands, clearance holes or other lay-out details concerning the surrounding of a via}
- 1/117 {Pads along the edge of rigid circuit boards, e.g. for pluggable connectors}
- 1/118 {specially for flexible printed circuits, e.g. using folded portions}
- 1/119 {Details of rigid insulating substrates therefor, e.g. three-dimensional details ([H05K 1/117 takes precedence](#))}
- 1/14 . . Structural association of two or more printed circuits ([providing electric connection to or between printed circuits H05K 1/11, H01R 12/00](#))
- 1/141 {One or more single auxiliary printed circuits mounted on a main printed circuit, e.g. modules, adapters ([H05K 1/142 and H05K 1/147 take precedence](#))}
- 1/142 {Arrangements of planar printed circuit boards in the same plane, e.g. auxiliary printed circuit insert mounted in a main printed circuit}
- 1/144 {Stacked arrangements of planar printed circuit boards}
- 1/145 {Arrangements wherein electric components are disposed between and simultaneously connected to two planar printed circuit boards, e.g. Cordwood modules}
- 1/147 {at least one of the printed circuits being bent or folded, e.g. by using a flexible printed circuit ([H05K 1/148 takes precedence](#))}
- 1/148 {Arrangements of two or more hingeably connected rigid printed circuit boards, i.e. connected by flexible means}
- 1/16 . . incorporating printed electric components, e.g. printed resistor, capacitor, inductor
- 1/162 {incorporating printed capacitors}
- 1/165 {incorporating printed inductors}
- 1/167 {incorporating printed resistors}
- 1/18 . . Printed circuits structurally associated with non-printed electric components ([H05K 1/0201, H05K 1/023, H05K 1/0243, and H05K 1/16 take precedence](#))
- 1/181 {associated with surface mounted components}
- 1/182 {associated with components mounted in the printed circuit board, e.g. insert mounted components [IMC]}
- 1/183 {Components mounted in and supported by recessed areas of the printed circuit board}
- 1/184 {Components including terminals inserted in holes through the printed circuit board and connected to printed contacts on the walls of the holes or at the edges thereof or protruding over or into the holes}
- 1/185 {Components encapsulated in the insulating substrate of the printed circuit or incorporated in internal layers of a multilayer circuit ([semiconductor chips encapsulated by interconnect and support structures H01L 23/5389, H01L 24/00](#))}
- 1/186 {manufactured by mounting on or connecting to patterned circuits before or during embedding}
- 1/187 {the patterned circuits being prefabricated circuits, which are not yet attached to a permanent insulating substrate, e.g. on a temporary carrier}
- 1/188 {manufactured by mounting on or attaching to a structure having a conductive layer, e.g. a metal foil, such that the terminals of the component are connected to or adjacent to the conductive layer before embedding, and by using the conductive layer, which is patterned after embedding, at least partially for connecting the component}
- 1/189 {characterised by the use of a flexible or folded printed circuit ([H05K 3/326 takes precedence](#))}
- 3/00 Apparatus or processes for manufacturing printed circuits**
- 3/0002 {for manufacturing artworks for printed circuits}
- 3/0005 {for designing circuits by computer}
- 3/0008 {for aligning or positioning of tools relative to the circuit board ([H05K 3/4638, H05K 3/4679 take precedence; for manufacturing assemblages of components H05K 13/0015](#))}
- 3/0011 {Working of insulating substrates or insulating layers}
- 3/0014 {Shaping of the substrate, e.g. by moulding}
- 3/0017 {Etching of the substrate by chemical or physical means}
- 3/002 {by liquid chemical etching}
- 3/0023 {by exposure and development of a photosensitive insulating layer}
- 3/0026 {by laser ablation}
- 3/0029 {of inorganic insulating material}
- 3/0032 {of organic insulating material}
- 3/0035 {of blind holes, i.e. having a metal layer at the bottom}
- 3/0038 {combined with laser drilling through a metal layer}
- 3/0041 {by plasma etching}
- 3/0044 {Mechanical working of the substrate, e.g. drilling or punching ([H05K 3/0008 takes precedence](#))}
- 3/0047 {Drilling of holes}
- 3/005 {Punching of holes}
- 3/0052 {Depaneling, i.e. dividing a panel into circuit boards; Working of the edges of circuit boards}

- 3/0055 . . {After-treatment, e.g. cleaning or desmearing of holes}
- 3/0058 . {Laminating printed circuit boards onto other substrates, e.g. metallic substrates ([H05K 1/0281](#) takes precedence)}
- 3/0061 . . {onto a metallic substrate, e.g. a heat sink ([heat sinks for electric apparatus H05K 7/20](#))}
- 3/0064 . . {onto a polymeric substrate}
- 3/0067 . . {onto an inorganic, non-metallic substrate}
- 3/007 . {Manufacture or processing of a substrate for a printed circuit board supported by a temporary or sacrificial carrier ([H05K 1/187](#), [H05K 3/20](#) and [H05K 3/4682](#) take precedence)}
- 3/0073 . {Masks not provided for in groups [H05K 3/02](#) - [H05K 3/46](#), e.g. for photomechanical production of patterned surfaces}
- 3/0076 . . {characterised by the composition of the mask}
- 3/0079 . . {characterised by the method of application or removal of the mask ([H05K 3/0091](#) takes precedence)}
- 3/0082 . . {characterised by the exposure method of radiation-sensitive masks}
- 3/0085 . {Apparatus for treatments of printed circuits with liquids not provided for in groups [H05K 3/02](#) - [H05K 3/46](#); conveyors and holding means therefor (apparatus specially adapted for manufacturing assemblages of electric components, e.g. printed circuit boards, [H05K 13/00](#))}
- 3/0088 . . {for treatment of holes}
- 3/0091 . {Apparatus for coating printed circuits using liquid non-metallic coating compositions}
- 3/0094 . {Filling or covering plated through-holes or blind plated vias, e.g. for masking or for mechanical reinforcement}
- 3/0097 . {Processing two or more printed circuits simultaneously, e.g. made from a common substrate, or temporarily stacked circuit boards ([H05K 3/0052](#) takes precedence)}
- 3/02 . in which the conductive material is applied to the surface of the insulating support and is thereafter removed from such areas of the surface which are not intended for current conducting or shielding
- 3/022 . . {Processes for manufacturing precursors of printed circuits, i.e. copper-clad substrates}
- 3/025 . . . {by transfer of thin metal foil formed on a temporary carrier, e.g. peel-apart copper}
- 3/027 . . {the conductive material being removed by irradiation, e.g. by photons, alpha or beta particles}
- 3/04 . . the conductive material being removed mechanically, e.g. by punching
- 3/041 . . . {by using a die for cutting the conductive material}
- 3/043 . . . {by using a moving tool for milling or cutting the conductive material}
- 3/045 . . . {by making a conductive layer having a relief pattern, followed by abrading of the raised portions}
- 3/046 . . . {by selective transfer or selective detachment of a conductive layer}
- 3/048 {using a lift-off resist pattern or a release layer pattern}
- 3/06 . . the conductive material being removed chemically or electrolytically, e.g. by photo-etch process {(semi-additive methods [H05K 3/108](#))}
- 3/061 . . . {Etching masks}
- 3/062 {consisting of metals or alloys or metallic inorganic compounds ([H05K 3/065](#) takes precedence)}
- 3/064 {Photoresists}
- 3/065 {applied by electrographic, electrophotographic or magnetographic methods}
- 3/067 . . . {Etchants}
- 3/068 . . . {Apparatus for etching printed circuits}
- 3/07 . . . being removed electrolytically
- 3/08 . . the conductive material being removed by electric discharge, e.g. by spark erosion
- 3/10 . in which conductive material is applied to the insulating support in such a manner as to form the desired conductive pattern
- 3/101 . . {by casting or moulding of conductive material}
- 3/102 . . {by bonding of conductive powder, i.e. metallic powder ([H05K 3/12](#) takes precedence)}
- 3/103 . . {by bonding or embedding conductive wires or strips}
- 3/105 . . {by conversion of non-conductive material on or in the support into conductive material, e.g. by using an energy beam}
- 3/106 . . . {by photographic methods}
- 3/107 . . {by filling grooves in the support with conductive material ([H05K 3/045](#), [H05K 3/101](#), [H05K 3/1258](#) and [H05K 3/465](#) take precedence)}
- 3/108 . . {by semi-additive methods; masks therefor (characterised by metallic etch mask [H05K 3/062](#); electroplating methods or apparatus [H05K 3/241](#))}
- 3/12 . . using {thick film techniques, e.g.} printing techniques to apply the conductive material {or similar techniques for applying conductive paste or ink patterns}
- 3/1208 . . . {Pretreatment of the circuit board, e.g. modifying wetting properties; Patterning by using affinity patterns ([providing shape patterns H05K 3/1258](#); [adhesion treatments H05K 3/38](#))}
- 3/1216 . . . {by screen printing or stencil printing}
- 3/1225 {Screens or stencils; Holders therefor}
- 3/1233 {Methods or means for supplying the conductive material and for forcing it through the screen or stencil}
- 3/1241 . . . {by ink-jet printing or drawing by dispensing}
- 3/125 {by ink-jet printing}
- 3/1258 . . . {by using a substrate provided with a shape pattern, e.g. grooves, banks, resist pattern}
- 3/1266 . . . {by electrographic or magnetographic printing}
- 3/1275 . . . {by other printing techniques, e.g. letterpress printing, intaglio printing, lithographic printing, offset printing}
- 3/1283 . . . {After-treatment of the printed patterns, e.g. sintering or curing methods}
- 3/1291 {Firing or sintering at relative high temperatures for patterns on inorganic boards, e.g. co-firing of circuits on green ceramic sheets}
- 3/14 . . using spraying techniques to apply the conductive material {, e.g. vapour evaporation}
- 3/143 . . . {Masks therefor ([H05K 3/048](#) takes precedence)}

- 3/146 . . . {By vapour deposition}
- 3/16 . . . by cathodic sputtering
- 3/18 . . using precipitation techniques to apply the conductive material
- 3/181 . . . {by electroless plating (adhesives therefor [H05K 3/387](#))}
- 3/182 {characterised by the patterning method}
- 3/184 {using masks}
- 3/185 {by making a catalytic pattern by photo-imaging}
- 3/187 {means therefor, e.g. baths, apparatus}
- 3/188 . . . {by direct electroplating}
- 3/20 . . by affixing prefabricated conductor pattern ([H05K 1/187](#), [H05K 3/046](#), [H05K 3/4658](#), [H05K 3/4682](#) takes precedence)
- 3/202 . . . {using self-supporting metal foil pattern}
- 3/205 . . . {using a pattern electroplated or electroformed on a metallic carrier}
- 3/207 . . . {using a prefabricated paste pattern, ink pattern or powder pattern}
- 3/22 . Secondary treatment of printed circuits ([H05K 3/1283](#) takes precedence; embedding circuits in grooves by pressure [H05K 3/107](#))
- 3/222 . . {Completing of printed circuits by adding non-printed jumper connections (printed jumper connections [H05K 3/4685](#))}
- 3/225 . . {Correcting or repairing of printed circuits ([H05K 1/0292](#), [H05K 3/222](#), [H05K 3/288](#), [H05K 3/4685](#) take precedence)}
- 3/227 . . {Drying of printed circuits}
- 3/24 . . Reinforcing the conductive pattern {(by solder coating [H05K 3/3457](#))}
- 3/241 . . . {characterised by the electroplating method; means therefor, e.g. baths or apparatus}
- 3/242 {characterised by using temporary conductors on the printed circuit for electrically connecting areas which are to be electroplated}
- 3/243 . . . {characterised by selective plating, e.g. for finish plating of pads (selective plating for making the circuit pattern [H05K 3/108](#), [H05K 3/182](#))}
- 3/244 . . . {Finish plating of conductors, especially of copper conductors, e.g. for pads or lands (selective plating methods [H05K 3/243](#); finish plating of conductors made by printing techniques [H05K 3/246](#); solder as finish [H05K 3/3457](#), e.g. by plating [H05K 3/3473](#))}
- 3/245 . . . {Reinforcing conductive patterns made by printing techniques or by other techniques for applying conductive pastes, inks or powders; Reinforcing other conductive patterns by such techniques}
- 3/246 {Reinforcing conductive paste, ink or powder patterns by other methods, e.g. by plating}
- 3/247 {Finish coating of conductors by using conductive pastes, inks or powders}
- 3/248 {fired compositions for inorganic substrates}
- 3/249 {comprising carbon particles as main constituent}
- 3/26 . . Cleaning or polishing of the conductive pattern
- 3/28 . . Applying non-metallic protective coatings ([H05K 3/0091](#) takes precedence; methods for intermediate insulating layers for build-up multilayer circuits [H05K 3/4673](#))}
- 3/281 . . . {by means of a preformed insulating foil ([H05K 3/284](#) takes precedence)}
- 3/282 . . . {for inhibiting the corrosion of the circuit, e.g. for preserving the solderability}
- 3/284 . . . {for encapsulating mounted components ([H05K 1/185](#) takes precedence)}
- 3/285 . . . {Permanent coating compositions}
- 3/287 {Photosensitive compositions}
- 3/288 . . . {Removal of non-metallic coatings, e.g. for repairing}
- 3/30 . Assembling printed circuits with electric components, e.g. with resistor
- 3/301 . . {by means of a mounting structure ([H05K 3/325](#) takes precedence)}
- 3/303 . . {Surface mounted components, e.g. affixing before soldering, aligning means, spacing means ([H05K 3/32](#) takes precedence)}
- 3/305 . . . {Affixing by adhesive}
- 3/306 . . {Lead-in-hole components, e.g. affixing or retention before soldering, spacing means ([H05K 3/32](#) takes precedence)}
- 3/308 . . . {Adaptations of leads (connectors to printed circuits [H01R 12/00](#))}
- 3/32 . . electrically connecting electric components or wires to printed circuits
- 3/321 . . . {by conductive adhesives}
- 3/323 {by applying an anisotropic conductive adhesive layer over an array of pads}
- 3/325 . . . {by abutting or pinching, i.e. without alloying process; mechanical auxiliary parts therefor (adaptations of leads inserted in holes for press-fit connections [H05K 3/308](#))}
- 3/326 {the printed circuit having integral resilient or deformable parts, e.g. tabs or parts of flexible circuits ([H05K 3/365](#) takes precedence)}
- 3/328 . . . {by welding}
- 3/34 . . . by soldering
- 3/3405 {Edge mounted components, e.g. terminals}
- 3/341 {Surface mounted components}
- 3/3415 {on both sides of the substrate or combined with lead-in-hole components}
- 3/3421 {Leaded components}
- 3/3426 {characterised by the leads}
- 3/3431 {Leadless components}
- 3/3436 {having an array of bottom contacts, e.g. pad grid array or ball grid array components}
- 3/3442 {having edge contacts, e.g. leadless chip capacitors, chip carriers}
- 3/3447 {Lead-in-hole components ([H05K 3/3415](#) takes precedence)}
- 3/3452 {Solder masks}
- 3/3457 {Solder materials or compositions; Methods of application thereof}
- 3/3463 {Solder compositions in relation to features of the printed circuit board or the mounting process}
- 3/3468 {Applying molten solder}
- 3/3473 {Plating of solder}

- 3/3478 {Applying solder preforms; Transferring prefabricated solder patterns}
- 3/3485 {Applying solder paste, slurry or powder (thick film methods for applying conductive paste or ink patterns [H05K 3/12](#))}
- 3/3489 {Composition of fluxes; Methods of application thereof; Other methods of activating the contact surfaces}
- 3/3494 {Heating methods for reflowing of solder (using integral heating means [H05K 1/0212](#))}
- 3/36 Assembling printed circuits with other printed circuits ([H05K 7/142](#) takes precedence)}
- 3/361 . . {Assembling flexible printed circuits with other printed circuits}
- 3/363 . . . {by soldering}
- 3/365 . . . {by abutting, i.e. without alloying process}
- 3/366 . . {substantially perpendicularly to each other ([H05K 3/361](#) takes precedence)}
- 3/368 . . {parallel to each other ([H05K 3/361](#) takes precedence)}
- 3/38 . . Improvement of the adhesion between the insulating substrate and the metal
- 3/381 . . {by special treatment of the substrate}
- 3/382 . . {by special treatment of the metal}
- 3/383 . . . {by microetching}
- 3/384 . . . {by plating}
- 3/385 . . . {by conversion of the surface of the metal, e.g. by oxidation, whether or not followed by reaction or removal of the converted layer}
- 3/386 . . {by the use of an organic polymeric bonding layer, e.g. adhesive}
- 3/387 . . . {for electroless plating ([H05K 3/4661](#) takes precedence)}
- 3/388 . . {by the use of a metallic or inorganic thin film adhesion layer}
- 3/389 . . {by the use of a coupling agent, e.g. silane}
- 3/40 . . Forming printed elements for providing electric connections to or between printed circuits
- 3/4007 . . {Surface contacts, e.g. bumps ([H05K 3/4092](#) takes precedence; deposition of finish layers on pads [H05K 3/24](#); forming solder bumps [H05K 3/3457](#))}
- 3/4015 . . . {using auxiliary conductive elements, e.g. pieces of metal foil, metallic spheres}
- 3/403 . . {Edge contacts; Windows or holes in the substrate having plural connections on the walls thereof ([H05K 3/4092](#) takes precedence)}
- 3/4038 . . {Through-connections; Vertical interconnect access [VIA] connections ([H05K 3/403](#), [H05K 3/42](#) take precedence)}
- 3/4046 . . . {using auxiliary conductive elements, e.g. metallic spheres, eyelets, pieces of wire}
- 3/4053 . . . {by thick-film techniques}
- 3/4061 {for via connections in inorganic insulating substrates}
- 3/4069 {for via connections in organic insulating substrates}
- 3/4076 . . . {by thin-film techniques}
- 3/4084 . . . {by deforming at least one of the conductive layers}
- 3/4092 . . {Integral conductive tabs, i.e. conductive parts partly detached from the substrate}
- 3/42 . . . Plated through-holes {or plated via connections}
- 3/421 . . . {Blind plated via connections ([H05K 3/422](#), [H05K 3/423](#) and [H05K 3/425](#) take precedence)}
- 3/422 . . . {characterised by electroless plating method; pretreatment therefor}
- 3/423 . . . {characterised by electroplating method}
- 3/424 {by direct electroplating}
- 3/425 . . . {characterised by the sequence of steps for plating the through-holes or via connections in relation to the conductive pattern}
- 3/426 {initial plating of through-holes in substrates without metal}
- 3/427 {initial plating of through-holes in metal-clad substrates}
- 3/428 {initial plating of through-holes in substrates having a metal pattern}
- 3/429 . . . {Plated through-holes specially for multilayer circuits, e.g. having connections to inner circuit layers}
- 3/44 . . Manufacturing insulated metal core circuits {or other insulated electrically conductive core circuits ([H05K 3/0058](#), [H05K 3/4608](#), and [H05K 3/4641](#) take precedence)}
- 3/445 . . {having insulated holes or insulated via connections through the metal core}
- 3/46 . . Manufacturing multilayer circuits
- 3/4602 . . {characterized by a special circuit board as base or central core whereon additional circuit layers are built or additional circuit boards are laminated}
- 3/4605 . . . {made from inorganic insulating material}
- 3/4608 . . . {comprising an electrically conductive base or core}
- 3/4611 . . {by laminating two or more circuit boards ([H05K 3/4652](#) takes precedence)}
- 3/4614 . . . {the electrical connections between the circuit boards being made during lamination}
- 3/4617 {characterized by laminating only or mainly similar single-sided circuit boards}
- 3/462 {characterized by laminating only or mainly similar double-sided circuit boards}
- 3/4623 . . . {the circuit boards having internal via connections between two or more circuit layers before lamination, e.g. double-sided circuit boards ([H05K 3/462](#) takes precedence)}
- 3/4626 . . . {characterised by the insulating layers or materials ([H05K 3/4688](#) takes precedence)}
- 3/4629 {laminating inorganic sheets comprising printed circuits, e.g. green ceramic sheets}
- 3/4632 {laminating thermoplastic or uncured resin sheets comprising printed circuits without added adhesive materials between the sheets}
- 3/4635 {laminating flexible circuit boards using additional insulating adhesive materials between the boards}
- 3/4638 . . . {Aligning and fixing the circuit boards before lamination; Detecting or measuring the misalignment after lamination; Aligning external circuit patterns or via connections relative to internal circuits}
- 3/4641 . . . {having integrally laminated metal sheets or special power cores}

H05K

- 3/4644 . . {by building the multilayer layer by layer, i.e. build-up multilayer circuits (making via holes in the insulating layers [H05K 3/0011](#); special circuit boards as base or core whereon the multilayer is built [H05K 3/4602](#))}
- 3/4647 . . . {by applying an insulating layer around previously made via studs}
- 3/465 . . . {by applying an insulating layer having channels for the next circuit layer}
- 3/4652 . . . {Adding a circuit layer by laminating a metal foil or a preformed metal foil pattern ([H05K 3/4647](#) takes precedence)}
- 3/4655 {by using a laminate characterized by the insulating layer (general-purpose insulating materials [H05K 1/03](#), [H05K 3/4673](#))}
- 3/4658 {characterized by laminating a prefabricated metal foil pattern, e.g. by transfer}
- 3/4661 . . . {Adding a circuit layer by direct wet plating, e.g. electroless plating; insulating materials adapted therefor (other insulating materials [H05K 3/387](#))}
- 3/4664 . . . {Adding a circuit layer by thick film methods, e.g. printing techniques or by other techniques for making conductive patterns by using pastes, inks or powders ([H05K 3/4647](#) takes precedence)}
- 3/4667 {characterized by using an inorganic intermediate insulating layer}
- 3/467 . . . {Adding a circuit layer by thin film methods ([H05K 3/4647](#) takes precedence)}
- 3/4673 . . . {Application methods or materials of intermediate insulating layers not specially adapted to any one of the previous methods of adding a circuit layer (similar methods for protective coatings [H05K 3/28](#))}
- 3/4676 {Single layer compositions}
- 3/4679 . . . {Aligning added circuit layers or via connections relative to previous circuit layers}
- 3/4682 . . . {Manufacture of core-less build-up multilayer circuits on a temporary carrier or on a metal foil}
- 3/4685 . . {Manufacturing of cross-over conductors}
- 3/4688 . . {Composite multilayer circuits, i.e. comprising insulating layers having different properties (having a special base or central core [H05K 3/4602](#))}
- 3/4691 . . . {Rigid-flexible multilayer circuits comprising rigid and flexible layers, e.g. having in the bending regions only flexible layers}
- 3/4694 . . . {Partitioned multilayer circuits having adjacent regions with different properties, e.g. by adding or inserting locally circuit layers having a higher circuit density ([H05K 3/4691](#) takes precedence)}
- 3/4697 . . {having cavities, e.g. for mounting components ([H05K 3/4691](#) takes precedence)}
- 5/00 Casings, cabinets or drawers for electric apparatus**
- 5/0017 . . {with operator interface units}
- WARNING**
Group [H05K 5/0017](#) is impacted by reclassification into group [H05K 5/0018](#).
Groups [H05K 5/0017](#) and [H05K 5/0018](#) should be considered in order to perform a complete search.
- 5/0018 . . {having an electronic display}
- WARNING**
Group [H05K 5/0018](#) is incomplete pending reclassification of documents from group [H05K 5/0017](#).
Groups [H05K 5/0017](#) and [H05K 5/0018](#) should be considered in order to perform a complete search.
- 5/0026 . . {provided with connectors and printed circuit boards [PCB], e.g. automotive electronic control units}
- 5/003 . . {having an integrally preformed housing}
- 5/0034 . . {having an overmolded housing covering the PCB}
- 5/0039 . . {having a tubular housing wherein the PCB is inserted longitudinally}
- 5/0043 . . {comprising a frame housing mating with two lids wherein the PCB is flat mounted on the frame housing}
- 5/0047 . . {having a two-part housing enclosing a PCB}
- 5/0052 . . . {characterized by joining features of the housing parts}
- 5/0056 . . . {characterized by features for protecting electronic components against vibration and moisture, e.g. potting, holders for relatively large capacitors}
- 5/006 . . . {characterized by features for holding the PCB within the housing}
- 5/0065 . . {wherein modules are associated together, e.g. electromechanical assemblies, modular structures}
- 5/0069 . . {having connector relating features for connecting the connector pins with the PCB or for mounting the connector body with the housing}
- 5/0073 . . {having specific features for mounting the housing on an external structure}
- 5/0078 . . {specially adapted for acceleration sensors, e.g. crash sensors, airbag sensors}
- 5/0082 . . {specially adapted for transmission control units, e.g. gearbox controllers}
- 5/0086 . . {portable, e.g. battery operated apparatus (casings for switching devices [H01H 9/02](#))}
- 5/0091 . . {Housing specially adapted for small components (for resistors [H01C](#); for capacitors [H01G](#); for integrated circuits [H01L 23/00](#))}
- 5/0095 . . {hermetically-sealed}

- 5/02 . . Details
 - WARNING**
 - Group [H05K 5/02](#) is impacted by reclassification into groups [H05K 5/0209](#), [H05K 5/021](#), [H05K 5/0211](#), [H05K 5/0212](#), [H05K 5/0214](#), [H05K 5/0215](#) and [H05K 5/0216](#).
 - All groups listed in this Warning should be considered in order to perform a complete search.
- 5/0204 . . {Mounting supporting structures on the outside of casings}
- 5/0208 . . {Interlock mechanisms; Means for avoiding unauthorised use or function, e.g. tamperproof}
- 5/0209 . . {Thermal insulation, e.g. for fire protection or for fire containment or for high temperature environments}
 - WARNING**
 - Groups [H05K 5/0209](#) - [H05K 5/0211](#) are incomplete pending reclassification of documents from groups [H05K 5/02](#) and [H05K 5/0213](#).
 - All groups listed in this Warning should be considered in order to perform a complete search.
- 5/021 . . . {specially adapted for data recorders, e.g. for flight recorders}
- 5/0211 . . . {Thermal buffers, e.g. latent heat absorbers}
- 5/0212 . . {Condensation eliminators}
 - WARNING**
 - Group [H05K 5/0212](#) is incomplete pending reclassification of documents from groups [H05K 5/02](#) and [H05K 5/0213](#).
 - Groups [H05K 5/02](#), [H05K 5/0213](#) and [H05K 5/0212](#) should be considered in order to perform a complete search.
- 5/0213 . . {Venting apertures; Constructional details thereof}
 - WARNING**
 - Group [H05K 5/0213](#) is impacted by reclassification into groups [H05K 5/0209](#), [H05K 5/021](#), [H05K 5/0211](#), [H05K 5/0212](#), [H05K 5/0214](#), [H05K 5/0215](#) and [H05K 5/0216](#).
 - All groups listed in this Warning should be considered in order to perform a complete search.
- 5/0214 . . . {with means preventing penetration of rain water or dust (semi-permeable membranes [H05K 5/0215](#), [H05K 5/0216](#))}
 - WARNING**
 - Group [H05K 5/0214](#) is incomplete pending reclassification of documents from groups [H05K 5/02](#) and [H05K 5/0213](#).
 - Groups [H05K 5/02](#), [H05K 5/0213](#) and [H05K 5/0214](#) should be considered in order to perform a complete search.
- 5/0215 . . . {with semi-permeable membranes attached to casings}
 - WARNING**
 - Group [H05K 5/0215](#) is incomplete pending reclassification of documents from groups [H05K 5/02](#) and [H05K 5/0213](#).
 - Groups [H05K 5/02](#), [H05K 5/0213](#) and [H05K 5/0215](#) should be considered in order to perform a complete search.
- 5/0216 . . . {Venting plugs comprising semi-permeable membranes}
 - WARNING**
 - Group [H05K 5/0216](#) is incomplete pending reclassification of documents from groups [H05K 5/02](#) and [H05K 5/0213](#).
 - Groups [H05K 5/02](#), [H05K 5/0213](#) and [H05K 5/0216](#) should be considered in order to perform a complete search.
- 5/0217 . . {Mechanical details of casings (covers, lids, hoods or members for covering apertures [H05K 5/03](#))}
- 5/0221 . . . {Locks; Latches}
- 5/0226 . . . {Hinges}
- 5/023 . . . {Handles; Grips}
- 5/0234 . . . {Feet; Stands; Pedestals, e.g. wheels for moving casing on floor}
- 5/0243 . . . {for decorative purposes}
- 5/0247 . . {Electrical details of casings, e.g. terminals, passages for cables or wiring}
- 5/0252 . . {Labels, e.g. for identification, markings or configuration store}
- 5/0256 . . {of interchangeable modules or receptacles therefor, e.g. cartridge mechanisms}
- 5/026 . . . {having standardized interfaces (flash memory cards [G06K 19/077](#))}
- 5/0265 {of PCMCIA type}
- 5/0269 {Card housings therefor, e.g. covers, frames, PCB}
- 5/0273 {having extensions for peripherals, e.g. LAN, antennas (details of antennas [H01Q 1/2275](#))}
- 5/0278 {of USB type (details relating to connectors [H01R 27/00](#))}
- 5/0282 . . . {Adapters for connecting cards having a first standard in receptacles having a second standard}
- 5/0286 . . . {Receptacles therefor, e.g. card slots, module sockets, card groundings}
- 5/0291 {for multiple cards}
- 5/0295 {having ejection mechanisms}
- 5/03 . . Covers
- 5/04 . Metal casings
- 5/06 . Hermetically-sealed casings ((specially adapted for small components [H05K 5/0095](#))}
- 5/061 . . {sealed by a gasket held between a removable cover and a body, e.g. O-ring, packing}
- 5/062 . . {sealed by a material injected between a non-removable cover and a body, e.g. hardening in situ}
- 5/063 . . {sealed by a labyrinth structure provided at the joining parts}

- 5/064 . . {sealed by potting, e.g. waterproof resin poured in a rigid casing}
- 5/065 . . {sealed by encapsulation, e.g. waterproof resin forming an integral casing, injection moulding}
- 5/066 . . {sealed by fusion of the joining parts without bringing material; sealed by brazing}
- 5/067 . . {containing a dielectric fluid}
- 5/068 . . {having a pressure compensation device, e.g. membrane (venting means [H05K 5/0213](#))}
- 5/069 . . {Other details of the casing, e.g. wall structure, passage for a connector, a cable, a shaft}
- 5/10 . comprising several parts forming a closed casing
- 5/13 . . assembled by screws
- 5/15 . . assembled by resilient members
- 5/30 . Side-by-side or stacked arrangements
- 7/00** **Constructional details common to different types of electric apparatus (casings, cabinets, drawers [H05K 5/00](#))**
- 7/005 . {arrangements of circuit components without supporting structure}
- 7/02 . Arrangements of circuit components or wiring on supporting structure
- 7/023 . . {Stackable modules}
- 7/026 . . {Multiple connections subassemblies}
- 7/04 . . on conductive chassis
- 7/06 . . on insulating boards {, e.g. wiring harnesses (for printed circuits [H05K 1/18](#), [H05K 3/30](#))}
- 7/08 . . . on perforated boards
- 7/10 . . Plug-in assemblages of components {, e.g. IC sockets}
- 7/1007 . . . {with means for increasing contact pressure at the end of engagement of coupling parts}
- 7/1015 . . . {having exterior leads}
- 7/1023 {co-operating by abutting, e.g. flat pack}
- 7/103 {co-operating by sliding, e.g. DIP carriers}
- 7/1038 {with spring contact pieces ([H05K 7/1046](#) takes precedence)}
- 7/1046 {J-shaped leads}
- 7/1053 {having interior leads}
- 7/1061 {co-operating by abutting}
- 7/1069 {with spring contact pieces}
- 7/1076 {co-operating by sliding}
- 7/1084 {pin grid array package carriers}
- 7/1092 . . . {with built-in components, e.g. intelligent sockets}
- 7/12 . . Resilient or clamping means for holding component to structure
- 7/14 . . Mounting supporting structure in casing or on frame or rack
- 7/1401 . . {comprising clamping or extracting means ([H05K 7/10](#) takes precedence)}
- 7/1402 . . . {for securing or extracting printed circuit boards}
- 7/1404 {by edge clamping, e.g. wedges}
- 7/1405 {by clips or resilient members, e.g. hooks}
- 7/1407 {by turn-bolt or screw member}
- 7/1408 {by a unique member which latches several boards, e.g. locking bars}
- 7/1409 {by lever-type mechanisms}
- 7/1411 {for securing or extracting box-type drawers}
- 7/1412 {hold down mechanisms, e.g. avionics racks}
- 7/1414 {with power interlock}
- 7/1415 {manual gripping tools}
- 7/1417 . . . {having securing means for mounting boards, plates or wiring boards ([H05K 7/1461](#) takes precedence)}
- 7/1418 {Card guides, e.g. grooves ([H05K 7/1425](#) takes precedence)}
- 7/142 {Spacers not being card guides}
- 7/1421 . . . {Drawers for printed circuit boards}
- 7/1422 . . . {Printed circuit boards receptacles, e.g. stacked structures, electronic circuit modules or box like frames}
- 7/1424 {Card cages}
- 7/1425 {of standardised dimensions, e.g. 19"-subrack}
- 7/1427 {Housings}
- 7/1428 {for small modular apparatus with terminal block}
- 7/1429 {for circuits carrying a CPU and adapted to receive expansion cards}
- 7/1431 {Retention mechanisms for CPU modules}
- 7/1432 {specially adapted for power drive units or power converters}

WARNING

Group [H05K 7/1432](#) is impacted by reclassification into groups [H05K 7/14322](#), [H05K 7/14324](#), [H05K 7/14325](#), [H05K 7/14327](#), [H05K 7/14329](#), [H05K 7/14337](#) and [H05K 7/14339](#).

All groups listed in this Warning should be considered in order to perform a complete search.

- 7/14322 {wherein the control and power circuits of a power converter are arranged within the same casing}

WARNING

Group [H05K 7/14322](#) is incomplete pending reclassification of documents from group [H05K 7/1432](#).

Groups [H05K 7/1432](#) and [H05K 7/14322](#) should be considered in order to perform a complete search.

- 7/14324 {comprising modular units, e.g. DIN rail mounted units}

WARNING

Group [H05K 7/14324](#) is incomplete pending reclassification of documents from group [H05K 7/1432](#).

Groups [H05K 7/1432](#) and [H05K 7/14324](#) should be considered in order to perform a complete search.

- 7/14325 {for cabinets or racks}
WARNING
 Group [H05K 7/14325](#) is incomplete pending reclassification of documents from group [H05K 7/1432](#).
 Groups [H05K 7/1432](#) and [H05K 7/14325](#) should be considered in order to perform a complete search.
- 7/14327 {having supplementary functional units, e.g. data transfer modules or displays or user interfaces}
WARNING
 Group [H05K 7/14327](#) is incomplete pending reclassification of documents from group [H05K 7/1432](#).
 Groups [H05K 7/1432](#) and [H05K 7/14327](#) should be considered in order to perform a complete search.
- 7/14329 {specially adapted for the configuration of power bus bars}
WARNING
 Group [H05K 7/14329](#) is incomplete pending reclassification of documents from group [H05K 7/1432](#).
 Groups [H05K 7/1432](#) and [H05K 7/14329](#) should be considered in order to perform a complete search.
- 7/14337 {specially adapted for underwater operation}
WARNING
 Group [H05K 7/14337](#) is incomplete pending reclassification of documents from group [H05K 7/1432](#).
 Groups [H05K 7/1432](#) and [H05K 7/14337](#) should be considered in order to perform a complete search.
- 7/14339 {specially adapted for high voltage operation}
WARNING
 Group [H05K 7/14339](#) is incomplete pending reclassification of documents from group [H05K 7/1432](#).
 Groups [H05K 7/1432](#) and [H05K 7/14339](#) should be considered in order to perform a complete search.
- 7/1434 {for electronics exposed to high gravitational force; Cylindrical housings}
- 7/1435 {Expandable constructions}
- 7/1438 {Back panels or connecting means therefor; Terminals; Coding means to avoid wrong insertion}
- 7/1439 {Back panel mother boards}
- 7/1441 {with a segmented structure}
- 7/1442 {with a radial structure}
- 7/1444 {Complex or three-dimensional-arrangements; Stepped or dual mother boards}
- 7/1445 {with double-sided connections}
- 7/1447 {External wirings; Wiring ducts; Laying cables}
- 7/1448 {with connections to the front board}
- 7/1449 {with connections to the back board}
- 7/1451 {with connections between circuit boards or units}
- 7/1452 {Mounting of connectors; Switching; Reinforcing of back panels}
- 7/1454 {Alignment mechanisms; Drawout cases}
- 7/1455 {Coding for prevention of wrong insertion}
- 7/1457 {Power distribution arrangements}
- 7/1458 {Active back panels; Back panels with filtering means}
- 7/1459 {Circuit configuration, e.g. routing signals}
- 7/1461 {Slidable card holders; Card stiffeners; Control or display means therefor}
- 7/1462 {for programmable logic controllers [PLC] for automation or industrial process control}
- 7/1464 {Functional units accommodated in the same PLC module housing}
- 7/1465 {Modular PLC assemblies with separable functional units}
- 7/1467 {PLC mounted in a cabinet or chassis}
- 7/1468 {Mechanical features of input/output (I/O) modules}
- 7/1469 {Terminal blocks for connecting sensors}
- 7/1471 {Modules for controlling actuators}
- 7/1472 {Bus coupling modules, e.g. bus distribution modules}
- 7/1474 {Mounting of modules, e.g. on a base or rail or wall}
- 7/1475 {Bus assemblies for establishing communication between PLC modules}
- 7/1477 {including backplanes}
- 7/1478 {including a segmented bus}
- 7/1479 {including decentralized modules, e.g. connected to other modules using fieldbus}
- 7/1481 {User interface, e.g. status displays; Programming interface, e.g. connector for computer programming; Monitoring}
- 7/1482 {PLC power supply; PLC accessories, e.g. for safety}
- 7/1484 {Electrical diagrams relating to constructional features, e.g. signal routing within PLC; Provisions for disaster recovery, e.g. redundant systems}
- 7/1485 {Servers; Data center rooms, e.g. 19-inch computer racks}
- 7/1487 {Blade assemblies, e.g. blade cases or inner arrangements within a blade}
- 7/1488 {Cabinets therefor, e.g. chassis or racks or mechanical interfaces between blades and support structures}
- 7/1489 {characterized by the mounting of blades therein, e.g. brackets, rails, trays ([H05K 7/1491](#) takes precedence)}
- 7/1491 {having cable management arrangements (management of optical cables [G02B 6/444](#); in telecommunication cabinets [H04Q 1/06](#))}
- 7/1492 {having electrical distribution arrangements, e.g. power supply or data communications}

- 7/1494 {having hardware for monitoring blades, e.g. keyboards, displays ([methods or software therefore H05K 7/1498](#))}
- 7/1495 {providing data protection in case of earthquakes, floods, storms, nuclear explosions, intrusions, fire}
- 7/1497 {Rooms for data centers; Shipping containers therefor}
- 7/1498 {Resource management, Optimisation arrangements, e.g. configuration, identification, tracking, physical location ([thermal management H05K 7/20836](#))}
- 7/16 on hinges or pivots
- 7/18 Construction of rack or frame
- 7/183 {support rails therefor}
- 7/186 {for supporting telecommunication equipment ([selecting apparatus H04Q 1/02](#))}
- 7/20 Modifications to facilitate cooling, ventilating, or heating
- 7/20009 {using a gaseous coolant in electronic enclosures ([in cabinets of standardized dimensions H05K 7/20536](#); [in server cabinets H05K 7/20709](#); [in vehicle electronic casings H05K 7/20845](#); [in power control electronics H05K 7/2089](#); [in displays H05K 7/20954](#))}
- 7/20127 {Natural convection}
- 7/20136 {Forced ventilation, e.g. by fans ([H05K 7/202 takes precedence](#))}
- 7/20145 {Means for directing air flow, e.g. ducts, deflectors, plenum or guides}
- 7/20154 {Heat dissipaters coupled to components}
- 7/20163 {the components being isolated from air flow, e.g. hollow heat sinks, wind tunnels or funnels}
- 7/20172 {Fan mounting or fan specifications}
- 7/20181 {Filters; Louvers}
- 7/2019 {Fan safe systems, e.g. mechanical devices for non stop cooling}
- 7/202 {Air circulating in closed loop within enclosure wherein heat is removed through heat-exchangers}
- 7/20209 {Thermal management, e.g. fan control}
- 7/20218 {using a liquid coolant without phase change in electronic enclosures ([in cabinets of standardized dimensions H05K 7/20536](#); [in server cabinets H05K 7/20709](#); [in vehicle electronic casings H05K 7/20845](#); [in power control electronics H05K 7/2089](#); [in displays H05K 7/20954](#))}
- 7/20236 {by immersion}
- 7/20245 {by natural convection; Thermosiphons}
- 7/20254 {Cold plates transferring heat from heat source to coolant}
- 7/20263 {Heat dissipaters releasing heat from coolant}
- 7/20272 {Accessories for moving fluid, for expanding fluid, for connecting fluid conduits, for distributing fluid, for removing gas or for preventing leakage, e.g. pumps, tanks or manifolds}
- 7/20281 {Thermal management, e.g. liquid flow control}
- 7/2029 {using a liquid coolant with phase change in electronic enclosures ([in cabinets of standardized dimensions H05K 7/20536](#); [in server cabinets H05K 7/20709](#); [in vehicle electronic casings H05K 7/20845](#); [in power control electronics H05K 7/2089](#); [in displays H05K 7/20954](#))}
- 7/203 {by immersion}
- 7/20309 {Evaporators}
- 7/20318 {Condensers}
- 7/20327 {Accessories for moving fluid, for connecting fluid conduits, for distributing fluid or for preventing leakage, e.g. pumps, tanks or manifolds}
- 7/20336 {Heat pipes, e.g. wicks or capillary pumps}
- 7/20345 {Sprayers; Atomizers}
- 7/20354 {Refrigerating circuit comprising a compressor}
- 7/20363 {Refrigerating circuit comprising a sorber}
- 7/20372 {Cryogenic cooling; Nitrogen liquid cooling}
- 7/20381 {Thermal management, e.g. evaporation control}
- 7/2039 {characterised by the heat transfer by conduction from the heat generating element to a dissipating body ([arrangements for increasing/decreasing heat-transfer, e.g. fins details, F28F 13/00](#))}
- 7/20409 {Outer radiating structures on heat dissipating housings, e.g. fins integrated with the housing}
- 7/20418 {the radiating structures being additional and fastened onto the housing}
- 7/20427 {having radiation enhancing surface treatment, e.g. black coating}
- 7/20436 {Inner thermal coupling elements in heat dissipating housings, e.g. protrusions or depressions integrally formed in the housing}
- 7/20445 {the coupling element being an additional piece, e.g. thermal standoff}
- 7/20454 {with a conformable or flexible structure compensating for irregularities, e.g. cushion bags, thermal paste}
- 7/20463 {Filling compound, e.g. potted resin}
- 7/20472 {Sheet interfaces}
- 7/20481 {characterised by the material composition exhibiting specific thermal properties}
- 7/2049 {Pressing means used to urge contact, e.g. springs}
- 7/205 {Heat-dissipating body thermally connected to heat generating element via thermal paths through printed circuit board [PCB] ([details of PCBs relating to heat transfer H05K 1/0201](#))}
- 7/20509 {Multiple-component heat spreaders; Multi-component heat-conducting support plates; Multi-component non-closed heat-conducting structures}
- 7/20518 {Unevenly distributed heat load, e.g. different sectors at different temperatures, localised cooling, hot spots}
- 7/20536 {for racks or cabinets of standardised dimensions, e.g. electronic racks for aircraft or telecommunication equipment}
- 7/20545 {Natural convection of gaseous coolant; Heat transfer by conduction from electronic boards}

- 7/20554 . . . {Forced ventilation of a gaseous coolant (in closed loop [H05K 7/206](#) or [H05K 7/20609](#) or [H05K 7/20618](#))}
- 7/20563 {within sub-racks for removing heat from electronic boards}
- 7/20572 {within cabinets for removing heat from sub-racks, e.g. plenum}
- 7/20581 {Cabinets including a drawer for fans}
- 7/2059 {within rooms for removing heat from cabinets, e.g. by air conditioning device}
- 7/206 . . . {Air circulating in closed loop within cabinets wherein heat is removed through air-to-air heat-exchanger}
- 7/20609 . . . {Air circulating in closed loop within cabinets wherein heat is removed through air-to-liquid heat-exchanger}
- 7/20618 . . . {Air circulating in different modes under control of air guidance flaps}
- 7/20627 . . . {Liquid coolant without phase change}
- 7/20636 {within sub-racks for removing heat from electronic boards}
- 7/20645 {within cabinets for removing heat from sub-racks}
- 7/20654 {within rooms for removing heat from cabinets}
- 7/20663 . . . {Liquid coolant with phase change, e.g. heat pipes}
- 7/20672 {within sub-racks for removing heat from electronic boards}
- 7/20681 {within cabinets for removing heat from sub-racks}
- 7/2069 {within rooms for removing heat from cabinets}
- 7/207 . . . {Thermal management, e.g. cabinet temperature control}
- 7/20709 . . {for server racks or cabinets; for data centers, e.g. 19-inch computer racks}
- 7/20718 . . . {Forced ventilation of a gaseous coolant (in closed loop [H05K 7/20754](#))}
- 7/20727 {within server blades for removing heat from heat source}
- 7/20736 {within cabinets for removing heat from server blades}
- 7/20745 {within rooms for removing heat from cabinets, e.g. by air conditioning device}
- 7/20754 . . . {Air circulating in closed loop within cabinets}
- 7/20763 . . . {Liquid cooling without phase change}
- 7/20772 {within server blades for removing heat from heat source}
- 7/20781 {within cabinets for removing heat from server blades}
- 7/2079 {within rooms for removing heat from cabinets}
- 7/208 . . . {Liquid cooling with phase change}
- 7/20809 {within server blades for removing heat from heat source}
- 7/20818 {within cabinets for removing heat from server blades}
- 7/20827 {within rooms for removing heat from cabinets, e.g. air conditioning devices}
- 7/20836 . . . {Thermal management, e.g. server temperature control}
- 7/20845 . . {for automotive electronic casings ([H05K 7/2089](#) takes precedence)}
- 7/20854 {Heat transfer by conduction from internal heat source to heat radiating structure ([H05K 7/20863](#) takes precedence)}
- 7/20863 {Forced ventilation, e.g. on heat dissipaters coupled to components}
- 7/20872 {Liquid coolant without phase change}
- 7/20881 {Liquid coolant with phase change}
- 7/2089 . . . {for power electronics, e.g. for inverters for controlling motor}
- 7/209 {Heat transfer by conduction from internal heat source to heat radiating structure ([H05K 7/20909](#) takes precedence)}
- 7/20909 {Forced ventilation, e.g. on heat dissipaters coupled to components}
- 7/20918 {the components being isolated from air flow, e.g. hollow heat sinks, wind tunnels or funnels}
- 7/20927 {Liquid coolant without phase change}
- 7/20936 {Liquid coolant with phase change}
- 7/20945 {Thermal management, e.g. inverter temperature control}
- 7/20954 . . . {for display panels}
- 7/20963 {Heat transfer by conduction from internal heat source to heat radiating structure ([H05K 7/20972](#) takes precedence)}
- 7/20972 {Forced ventilation, e.g. on heat dissipaters coupled to components}
- 7/20981 {Liquid coolant without phase change}
- 7/2099 {Liquid coolant with phase change}
- 9/00 Screening of apparatus or components against electric or magnetic fields (devices for absorbing radiation from an antenna [H01Q 17/00](#))**
- 9/0001 . . {Rooms or chambers ([anechoic chambers G01R 29/0821](#))}
- 9/0003 . . . {Shielded walls, floors, ceilings, e.g. wallpaper, wall panel, electro-conductive plaster, concrete, cement, mortar}
- 9/0005 . . . {Shielded windows}
- 9/0007 . . {Casings ([standardised racks H05K 9/0062](#))}
- 9/0009 . . . {with provisions to reduce EMI leakage through the joining parts}
- 9/0015 . . . {Gaskets or seals}
- 9/0016 . . . {having a spring contact}
- 9/0018 . . . {with provisions to reduce aperture leakages in walls, e.g. terminals, connectors, cables}
- 9/002 . . . {with localised screening}
- 9/0022 {of components mounted on printed circuit boards [PCB] ([shields integrated within component packages H01L 23/552](#); [shields integrated within PCB H05K 1/0218](#))}
- 9/0024 {Shield cases mounted on a PCB, e.g. cans or caps or conformal shields}
- WARNING**
- Group [H05K 9/0024](#) is impacted by reclassification into groups [H05K 9/0029](#) and [H05K 9/0031](#).
- Groups [H05K 9/0024](#), [H05K 9/0029](#) and [H05K 9/0031](#) should be considered in order to perform a complete search.
- 9/0026 {integrally formed from metal sheet}
- 9/0028 {with retainers or specific soldering features}

- 9/0029 {made from non-conductive materials intermixed with electro-conductive particles ([H05K 9/0031](#) takes precedence)}
- WARNING**
- Group [H05K 9/0029](#) is incomplete pending reclassification of documents from groups [H05K 9/0024](#) and [H05K 9/003](#).
- All groups listed in this Warning should be considered in order to perform a complete search.
- 9/003 {made from non-conductive materials comprising an electro-conductive coating ([H05K 9/0031](#) takes precedence)}
- WARNING**
- Group [H05K 9/003](#) is impacted by reclassification into groups [H05K 9/0029](#) and [H05K 9/0031](#).
- Groups [H05K 9/003](#), [H05K 9/0029](#) and [H05K 9/0031](#) should be considered in order to perform a complete search.
- 9/0031 {combining different shielding materials}
- WARNING**
- Group [H05K 9/0031](#) is incomplete pending reclassification of documents from groups [H05K 9/0024](#) and [H05K 9/003](#).
- All groups listed in this Warning should be considered in order to perform a complete search.
- 9/0032 {having multiple parts, e.g. frames mating with lids}
- 9/0033 {disposed on both PCB faces}
- 9/0035 {with retainers mounted beforehand on the PCB, e.g. clips}
- 9/0037 {Housings with compartments containing a PCB, e.g. partitioning walls}
- 9/0039 {Galvanic coupling of ground layer on printed circuit board [PCB] to conductive casing ([printed shielding conductors, ground planes or power planes for reduction of cross-talk or noise in printed circuits H05K 1/0218](#))}
- 9/0041 . . {Ventilation panels having provisions for screening}
- 9/0043 . . {being flexible containers, e.g. pouch, pocket, bag}
- 9/0045 . . {being rigid plastic containers having a coating of shielding material}
- 9/0047 . . {being rigid plastic containers having conductive particles, fibres or mesh embedded therein}
- 9/0049 . . {being metallic containers}
- 9/005 . . {being nesting containers}
- 9/0052 . . {Shielding other than Faraday cages}
- 9/0054 . . {specially adapted for display applications}
- 9/0056 . . {specially adapted for microwave applications}
- 9/0058 . . {specially adapted for optoelectronic applications}
- 9/006 . . {specially adapted for signal processing applications, e.g. CATV, tuner, antennas amplifier}
- 9/0062 . . {Structures of standardised dimensions, e.g. 19" rack, chassis for servers or telecommunications}
- 9/0064 . . {Earth or grounding circuit}
- 9/0066 . . {Constructional details of transient suppressor}
- 9/0067 . . {Devices for protecting against damage from electrostatic discharge}
- 9/0069 . . {Methods for measuring the shielding efficiency; Apparatus therefor; Isolation container for testing}
- 9/0071 . . {Active shielding}
- 9/0073 . . {Shielding materials ([H05K 9/0003](#) takes precedence)}
- 9/0075 . . {Magnetic shielding materials}
- 9/0077 {comprising superconductors}
- 9/0079 . . {Electrostatic discharge protection, e.g. ESD treated surface for rapid dissipation of charges}
- 9/0081 . . {Electromagnetic shielding materials, e.g. EMI, RFI shielding ([H05K 9/0003](#) takes precedence)}
- 9/0083 {comprising electro-conductive non-fibrous particles embedded in an electrically insulating supporting structure, e.g. powder, flakes, whiskers ([H05K 9/0086](#) takes precedence)}
- 9/0084 {comprising a single continuous metallic layer on an electrically insulating supporting structure, e.g. metal foil, film, plating coating, electro-deposition, vapour-deposition}
- 9/0086 {comprising a single discontinuous metallic layer on an electrically insulating supporting structure, e.g. metal grid, perforated metal foil, film, aggregated flakes, sintering}
- 9/0088 {comprising a plurality of shielding layers; combining different shielding material structure}
- 9/009 {comprising electro-conductive fibres, e.g. metal fibres, carbon fibres, metallised textile fibres, electro-conductive mesh, woven, non-woven mat, fleece, cross-linked}
- 9/0092 {comprising electro-conductive pigments, e.g. paint, ink, tampon printing}
- 9/0094 . . {being light-transmitting, e.g. transparent, translucent}
- 9/0096 {for television displays, e.g. plasma display panel}
- 9/0098 . . {for shielding electrical cables}
- 10/00 Arrangements for improving the operating reliability of electronic equipment, e.g. by providing a similar standby unit**
- 11/00 Combinations of a radio or television receiver with apparatus having a different main function** {([combined with clocks G04B 47/00](#); [controlled by a clock G04C 21/28](#))}
- 11/02 . . with vehicles
- 13/00 Apparatus or processes specially adapted for manufacturing or adjusting assemblages of electric components**
- 13/0007 . . {using handtools ([for mounting on a circuit board H05K 13/0447](#))}
- 13/0015 . . {Orientation; Alignment; Positioning}
- 13/003 . . {Placing of components on belts holding the terminals}
- 13/0038 . . {placing the components in a predetermined order}

- 13/0053 . . {Arrangements for assisting the manual mounting of components, e.g. special tables or light spots indicating the place for mounting}
- 13/0061 . . {Tools for holding the circuit boards during processing; handling transport of printed circuit boards}
- 13/0069 . . {Holders for printed circuit boards}
- 13/0076 . . {Straightening or aligning terminal leads of pins mounted on boards, during transport of the boards}
- 13/0084 . . {Containers and magazines for components, e.g. tube-like magazines}
- 13/0092 . . {Treatment of the terminal leads as a separate operation (during transport [H05K 13/0076](#), [H05K 13/023](#); during mounting [H05K 13/04](#))}
- 13/02 . . Feeding of components
- 13/021 . . . {Loading or unloading of containers ([H05K 13/028](#) takes precedence)}
- 13/0215 . . . {Interconnecting of containers, e.g. splicing of tapes}
- 13/022 . . . {with orientation of the elements}
- 13/023 . . . {with bending or straightening of the terminal leads}
- 13/024 {Straightening or aligning terminal leads}
- 13/025 {of components having oppositely extending terminal leads}
- 13/026 {of components having terminal leads in side by side relationship, e.g. using combing elements}
- 13/027 . . . {Fluid transport of components}
- 13/028 . . . {Simultaneously loading a plurality of loose objects, e.g. by means of vibrations, pressure differences, magnetic fields}
- 13/029 . . . {Feeding axial lead components, e.g. using vibrating bowls, magnetic fields ([H05K 13/022](#) takes precedence)}
- 13/04 . . . Mounting of components {, e.g. of leadless components}
- 13/0404 . . . {Pick-and-place heads or apparatus, e.g. with jaws}
- 13/0406 {Drive mechanisms for pick-and-place heads, e.g. details relating to power transmission, motors or vibration damping}
- 13/0408 {Incorporating a pick-up tool}
- 13/0409 {Sucking devices}
- 13/041 {having multiple pick-up tools}
- 13/0411 {having multiple mounting heads}
- 13/0413 {with orientation of the component while holding it; Drive mechanisms for gripping tools, e.g. lifting, lowering or turning of gripping tools}
- 13/0417 {Feeding with belts or tapes}
- 13/0419 {tape feeders}
- 13/0421 {with treatment of the terminal leads}
- 13/0426 {for components being oppositely extending terminal leads ([H05K 13/0421](#) takes precedence)}
- 13/043 {Feeding one by one by other means than belts}
- 13/0434 {with containers}
- 13/0439 {incorporating means for treating the terminal leads only before insertion}
- 13/0443 {incorporating means for treating the terminal leads before and after insertion or only after insertion}
- 13/0447 {Hand tools therefor}
- 13/0452 {Mounting machines or lines comprising a plurality of tools for guiding different components to the same mounting place ([H05K 13/0406](#), [H05K 13/041](#) take precedence)}
- 13/0456 {simultaneously punching the circuit board}
- 13/046 {Surface mounting ([surface mounted components H05K 3/341](#))}
- 13/0465 {by soldering ([H05K 13/0469](#) takes precedence)}
- 13/0469 {by applying a glue or viscous material}
- 13/0473 {Cutting and clinching the terminal ends of the leads after they are fitted on a circuit board}
- 13/0478 {Simultaneously mounting of different components}
- 13/0482 {using templates; using magazines, the configuration of which corresponds to the sites on the boards where the components have to be attached}
- 13/0486 {Replacement and removal of components}
- 13/0491 {Hand tools therefor}
- 13/0495 {having a plurality of work-stations}
- 13/06 Wiring by machine
- 13/065 {Accessories therefor, e.g. light spots}
- 13/08 Monitoring manufacture of assemblages
- 13/081 {Integration of optical monitoring devices in assembly lines; Processes using optical monitoring devices specially adapted for controlling devices or machines in assembly lines}
- 13/0812 {the monitoring devices being integrated in the mounting machine, e.g. for monitoring components, leads, component placement}
- 13/0813 {Controlling of single components prior to mounting, e.g. orientation, component geometry ([H05K 13/0812](#) takes precedence)}
- 13/0815 {Controlling of component placement on the substrate during or after manufacturing}
- 13/0817 {Monitoring of soldering processes ([inspection of solder joints or of printed solder paste G01N 21/95684](#))}
- 13/0818 {Setup of monitoring devices prior to starting mounting operations; Teaching of monitoring devices for specific products; Compensation of drifts during operation, e.g. due to temperature shifts}
- 13/082 {Integration of non-optical monitoring devices, i.e. using non-optical inspection means, e.g. electrical means, mechanical means or X-rays}
- 13/083 {Quality monitoring using results from monitoring devices, e.g. feedback loops ([H05K 13/084](#) takes precedence)}
- 13/084 {Product tracking, e.g. of substrates during the manufacturing process; Component traceability}
- 13/085 {Production planning, e.g. of allocation of products to machines, of mounting sequences at machine or facility level}
- 13/0853 {Determination of transport trajectories inside mounting machines}
- 13/0857 {Product-specific machine setup; Changeover of machines or assembly lines to new product type}
- 13/086 {Supply management, e.g. supply of components or of substrates}

- 13/087 . . {Equipment tracking or labelling, e.g. tracking of nozzles, feeders or mounting heads}
- 13/0882 . . {Control systems for mounting machines or assembly lines, e.g. centralized control, remote links, programming of apparatus and processes as such ([H05K 13/083](#) takes precedence)}
- 13/0885 . . {Power supply}
- 13/0888 . . {Ergonomics; Operator safety; Training; Failsafe systems}
- 13/089 . . {Calibration, teaching or correction of mechanical systems, e.g. of the mounting head}
- 13/0895 . . {Maintenance systems or processes, e.g. indicating need for maintenance}
- 2201/00 Indexing scheme relating to printed circuits covered by [H05K 1/00](#)**
- 2201/01 . Dielectrics
- 2201/0104 . . Properties and characteristics in general
- 2201/0108 . . . Transparent
- 2201/0112 . . . Absorbing light, e.g. dielectric layer with carbon filler for laser processing
- 2201/0116 . . . Porous, e.g. foam
- 2201/012 . . . Flame-retardant; Preventing of inflammation
- 2201/0125 . . . Shrinkable, e.g. heat-shrinkable polymer
- 2201/0129 . . . Thermoplastic polymer, e.g. auto-adhesive layer; Shaping of thermoplastic polymer
- 2201/0133 . . . Elastomeric or compliant polymer
- 2201/0137 . . Materials
- 2201/0141 . . . Liquid crystal polymer [LCP]
- 2201/0145 . . . Polyester, e.g. polyethylene terephthalate [PET], polyethylene naphthalate [PEN]
- 2201/015 . . . Fluoropolymer, e.g. polytetrafluoroethylene [PTFE]
- 2201/0154 . . . Polyimide
- 2201/0158 . . . Polyalkene or polyolefin, e.g. polyethylene [PE], polypropylene [PP]
- 2201/0162 . . . Silicon containing polymer, e.g. silicone
- 2201/0166 . . . Polymeric layer used for special processing, e.g. resist for etching insulating material or photoresist used as a mask during plasma etching
- 2201/017 . . . Glass ceramic coating, e.g. formed on inorganic substrate
- 2201/0175 . . . Inorganic, non-metallic layer, e.g. resist or dielectric for printed capacitor
- 2201/0179 . . . Thin film deposited insulating layer, e.g. inorganic layer for printed capacitor
- 2201/0183 . . Dielectric layers
- 2201/0187 . . . with regions of different dielectrics in the same layer, e.g. in a printed capacitor for locally changing the dielectric properties
- 2201/0191 . . . wherein the thickness of the dielectric plays an important role
- 2201/0195 . . . Dielectric or adhesive layers comprising a plurality of layers, e.g. in a multilayer structure
- 2201/02 . Fillers; Particles; Fibers; Reinforcement materials
- 2201/0203 . . Fillers and particles
- 2201/0206 . . . Materials
- 2201/0209 Inorganic, non-metallic particles
- 2201/0212 Resin particles
- 2201/0215 Metallic fillers
- 2201/0218 Composite particles, i.e. first metal coated with second metal
- 2201/0221 Insulating particles having an electrically conductive coating
- 2201/0224 Conductive particles having an insulating coating
- 2201/0227 Insulating particles having an insulating coating
- 2201/023 Hard particles, i.e. particles in conductive adhesive at least partly penetrating an electrode
- 2201/0233 Deformable particles
- 2201/0236 Plating catalyst as filler in insulating material
- 2201/0239 Coupling agent for particles
- 2201/0242 . . . Shape of an individual particle
- 2201/0245 Flakes, flat particles or lamellar particles
- 2201/0248 Needles or elongated particles; Elongated cluster of chemically bonded particles
- 2201/0251 Non-conductive microfibers
- 2201/0254 Microballoons or hollow filler particles
- 2201/0257 Nanoparticles
- 2201/026 Nanotubes or nanowires
- 2201/0263 . . . Details about a collection of particles
- 2201/0266 Size distribution
- 2201/0269 Non-uniform distribution or concentration of particles
- 2201/0272 Mixed conductive particles, i.e. using different conductive particles, e.g. differing in shape
- 2201/0275 . . Fibers and reinforcement materials
- 2201/0278 . . . Polymeric fibers
- 2201/0281 . . . Conductive fibers
- 2201/0284 . . . Paper, e.g. as reinforcement
- 2201/0287 . . . Unidirectional or parallel fibers
- 2201/029 . . . Woven fibrous reinforcement or textile
- 2201/0293 . . . Non-woven fibrous reinforcement
- 2201/0296 . . . Fibers with a special cross-section, e.g. elliptical
- 2201/03 . Conductive materials
- 2201/0302 . . Properties and characteristics in general
- 2201/0305 . . . Solder used for other purposes than connections between PCB or components, e.g. for filling vias or for programmable patterns
- 2201/0308 . . . Shape memory alloy [SMA]
- 2201/0311 . . . Metallic part with specific elastic properties, e.g. bent piece of metal as electrical contact
- 2201/0314 . . . Elastomeric connector or conductor, e.g. rubber with metallic filler
- 2201/0317 . . . Thin film conductor layer; Thin film passive component
- 2201/032 . . Materials
- 2201/0323 . . . Carbon
- 2201/0326 . . . Inorganic, non-metallic conductor, e.g. indium-tin oxide [ITO]
- 2201/0329 . . . Intrinsically conductive polymer [ICP]; Semiconductive polymer
- 2201/0332 . . Structure of the conductor
- 2201/0335 . . . Layered conductors or foils
- 2201/0338 Layered conductor, e.g. layered metal substrate, layered finish layer or layered thin film adhesion layer
- 2201/0341 Intermediate metal, e.g. before reinforcing of conductors by plating
- 2201/0344 Electroless sublayer, e.g. Ni, Co, Cd or Ag; Transferred electroless sublayer

- 2201/0347 Overplating, e.g. for reinforcing conductors or bumps; Plating over filled vias
- 2201/035 Paste overlayer, i.e. conductive paste or solder paste over conductive layer
- 2201/0352 Differences between the conductors of different layers of a multilayer
- 2201/0355 Metal foils
- 2201/0358 Resin coated copper [RCC]
- 2201/0361 Etched tri-metal structure, i.e. metal layers or metal patterns on both sides of a different central metal layer which is later at least partly etched
- 2201/0364 Conductor shape
- 2201/0367 Metallic bump or raised conductor not used as solder bump
- 2201/037 Hollow conductors, i.e. conductors partially or completely surrounding a void, e.g. hollow waveguides
- 2201/0373 Conductors having a fine structure, e.g. providing a plurality of contact points with a structured tool
- 2201/0376 Flush conductors, i.e. flush with the surface of the printed circuit
- 2201/0379 Stacked conductors
- 2201/0382 Continuously deformed conductors
- 2201/0385 Displaced conductors
- 2201/0388 Other aspects of conductors
- 2201/0391 Using different types of conductors
- 2201/0394 Conductor crossing over a hole in the substrate or a gap between two separate substrate parts
- 2201/0397 Tab
- 2201/04 Assemblies of printed circuits
- 2201/041 Stacked PCBs, i.e. having neither an empty space nor mounted components in between
- 2201/042 Stacked spaced PCBs; Planar parts of folded flexible circuits having mounted components in between or spaced from each other
- 2201/043 Stacked PCBs with their backs attached to each other without electrical connection
- 2201/044 Details of backplane or midplane for mounting orthogonal PCBs
- 2201/045 Hierarchy auxiliary PCB, i.e. more than two levels of hierarchy for daughter PCBs are important
- 2201/046 Planar parts of folded PCBs making an angle relative to each other
- 2201/047 Box-like arrangements of PCBs
- 2201/048 Second PCB mounted on first PCB by inserting in window or holes of the first PCB
- 2201/049 PCB for one component, e.g. for mounting onto mother PCB
- 2201/05 Flexible printed circuits [FPCs]
- 2201/051 Rolled
- 2201/052 Branched
- 2201/053 Tails
- 2201/055 Folded back on itself
- 2201/056 Folded around rigid support or component
- 2201/057 Shape retainable
- 2201/058 Direct connection between two or more FPCs or between flexible parts of rigid PCBs
- 2201/06 Thermal details
- 2201/062 Means for thermal insulation, e.g. for protection of parts
- 2201/064 Fluid cooling, e.g. by integral pipes
- 2201/066 Heatsink mounted on the surface of the printed circuit board [PCB]
- 2201/068 wherein the coefficient of thermal expansion is important
- 2201/07 Electric details
- 2201/0707 Shielding
- 2201/0715 provided by an outer layer of PCB
- 2201/0723 provided by an inner layer of PCB
- 2201/073 High voltage adaptations
- 2201/0738 Use of voltage responsive materials, e.g. voltage switchable dielectric or varistor materials
- 2201/0746 Protection against transients, e.g. layout adapted for plugging of connector
- 2201/0753 Insulation
- 2201/0761 Insulation resistance, e.g. of the surface of the PCB between the conductors
- 2201/0769 Anti metal-migration, e.g. avoiding tin whisker growth
- 2201/0776 Resistance and impedance
- 2201/0784 Uniform resistance, i.e. equalizing the resistance of a number of conductors
- 2201/0792 Means against parasitic impedance; Means against eddy currents
- 2201/08 Magnetic details
- 2201/083 Magnetic materials
- 2201/086 for inductive purposes, e.g. printed inductor with ferrite core
- 2201/09 Shape and layout
- 2201/09009 Substrate related
- 2201/09018 Rigid curved substrate
- 2201/09027 Non-rectangular flat PCB, e.g. circular
- 2201/09036 Recesses or grooves in insulating substrate
- 2201/09045 Locally raised area or protrusion of insulating substrate
- 2201/09054 Raised area or protrusion of metal substrate
- 2201/09063 Holes or slots in insulating substrate not used for electrical connections
- 2201/09072 Hole or recess under component or special relationship between hole and component
- 2201/09081 Tongue or tail integrated in planar structure, e.g. obtained by cutting from the planar structure
- 2201/0909 Preformed cutting or breaking line
- 2201/091 Locally and permanently deformed areas including dielectric material
- 2201/09109 Locally detached layers, e.g. in multilayer
- 2201/09118 Moulded substrate
- 2201/09127 PCB or component having an integral separable or breakable part
- 2201/09136 Means for correcting warpage
- 2201/09145 Edge details
- 2201/09154 Bevelled, chamfered or tapered edge
- 2201/09163 Slotted edge
- 2201/09172 Notches between edge pads
- 2201/09181 Notches in edge pads
- 2201/0919 Exposing inner circuit layers or metal planes at the side edge of the printed circuit board [PCB] or at the walls of large holes

- 2201/092 . . . Exposing inner circuit layers or metal planes at the walls of high aspect ratio holes
- 2201/09209 . . Shape and layout details of conductors
- 2201/09218 . . . Conductive traces
- 2201/09227 Layout details of a plurality of traces, e.g. escape layout for Ball Grid Array [BGA] mounting
- 2201/09236 Parallel layout
- 2201/09245 Crossing layout
- 2201/09254 Branched layout
- 2201/09263 Meander
- 2201/09272 Layout details of angles or corners
- 2201/09281 Layout details of a single conductor
- 2201/0929 . . . Conductive planes
- 2201/093 Layout of power planes, ground planes or power supply conductors, e.g. having special clearance holes therein
- 2201/09309 Core having two or more power planes; Capacitive laminate of two power planes
- 2201/09318 Core having one signal plane and one power plane
- 2201/09327 Special sequence of power, ground and signal layers in multilayer PCB
- 2201/09336 Signal conductors in same plane as power plane
- 2201/09345 Power and ground in the same plane; Power planes for two voltages in one plane
- 2201/09354 Ground conductor along edge of main surface
- 2201/09363 wherein only contours around conductors are removed for insulation
- 2201/09372 . . . Pads and lands
- 2201/09381 Shape of non-curved single flat metallic pad, land or exposed part thereof; Shape of electrode of leadless component
- 2201/0939 Curved pads, e.g. semi-circular or elliptical pads or lands
- 2201/094 Array of pads or lands differing from one another, e.g. in size, pitch or thickness; Using different connections on the pads
- 2201/09409 Multiple rows of pads, lands, terminals or dummy patterns; Multiple rows of mounted components
- 2201/09418 Special orientation of pads, lands or terminals of component, e.g. radial or polygonal orientation
- 2201/09427 Special relation between the location or dimension of a pad or land and the location or dimension of a terminal
- 2201/09436 Pads or lands on permanent coating which covers the other conductors
- 2201/09445 Pads for connections not located at the edge of the PCB, e.g. for flexible circuits
- 2201/09454 Inner lands, i.e. lands around via or plated through-hole in internal layer of multilayer PCB
- 2201/09463 Partial lands, i.e. lands or conductive rings not completely surrounding the hole
- 2201/09472 Recessed pad for surface mounting; Recessed electrode of component
- 2201/09481 Via in pad; Pad over filled via
- 2201/0949 Pad close to a hole, not surrounding the hole
- 2201/095 . . . Conductive through-holes or vias
- 2201/09509 Blind vias, i.e. vias having one side closed
- 2201/09518 Deep blind vias, i.e. blind vias connecting the surface circuit to circuit layers deeper than the first buried circuit layer
- 2201/09527 Inverse blind vias, i.e. bottoms outwards in multilayer PCB; Blind vias in centre of PCB having opposed bottoms
- 2201/09536 Buried plated through-holes, i.e. plated through-holes formed in a core before lamination
- 2201/09545 Plated through-holes or blind vias without lands
- 2201/09554 Via connected to metal substrate
- 2201/09563 Metal filled via
- 2201/09572 Solder filled plated through-hole in the final product
- 2201/09581 Applying an insulating coating on the walls of holes
- 2201/0959 Plated through-holes or plated blind vias filled with insulating material
- 2201/096 Vertically aligned vias, holes or stacked vias
- 2201/09609 Via grid, i.e. two-dimensional array of vias or holes in a single plane
- 2201/09618 Via fence, i.e. one-dimensional array of vias
- 2201/09627 Special connections between adjacent vias, not for grounding vias
- 2201/09636 Details of adjacent, not connected vias
- 2201/09645 Patterning on via walls; Plural lands around one hole
- 2201/09654 covering at least two types of conductors provided for in [H05K 2201/09218](#) - [H05K 2201/095](#)
- 2201/09663 Divided layout, i.e. conductors divided in two or more parts
- 2201/09672 Superposed layout, i.e. in different planes
- 2201/09681 Mesh conductors, e.g. as a ground plane
- 2201/0969 Apertured conductors
- 2201/097 Alternating conductors, e.g. alternating different shaped pads, twisted pairs; Alternating components
- 2201/09709 Staggered pads, lands or terminals; Parallel conductors in different planes
- 2201/09718 Clearance holes
- 2201/09727 Varying width along a single conductor; Conductors or pads having different widths
- 2201/09736 Varying thickness of a single conductor; Conductors in the same plane having different thicknesses
- 2201/09745 Recess in conductor, e.g. in pad or in metallic substrate
- 2201/09754 Connector integrally incorporated in the printed circuit board [PCB] or in housing
- 2201/09763 Printed component having superposed conductors, but integrated in one circuit layer
- 2201/09772 Conductors directly under a component but not electrically connected to the component
- 2201/09781 Dummy conductors, i.e. not used for normal transport of current; Dummy electrodes of components
- 2201/0979 Redundant conductors or connections, i.e. more than one current path between two points
- 2201/098 Special shape of the cross-section of conductors, e.g. very thick plated conductors
- 2201/09809 Coaxial layout

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- 2201/09818 . . Shape or layout details not covered by a single group of [H05K 2201/09009](#) - [H05K 2201/09809](#)
- 2201/09827 . . . Tapered, e.g. tapered hole, via or groove
- 2201/09836 . . . Oblique hole, via or bump
- 2201/09845 . . . Stepped hole, via, edge, bump or conductor
- 2201/09854 . . . Hole or via having special cross-section, e.g. elliptical
- 2201/09863 . . . Concave hole or via
- 2201/09872 . . . Insulating conformal coating
- 2201/09881 . . . Coating only between conductors, i.e. flush with the conductors
- 2201/0989 . . . Coating free areas, e.g. areas other than pads or lands free of solder resist
- 2201/099 . . . Coating over pads, e.g. solder resist partly over pads
- 2201/09909 . . . Special local insulating pattern, e.g. as dam around component
- 2201/09918 . . . Optically detected marks used for aligning tool relative to the PCB, e.g. for mounting of components
- 2201/09927 . . . Machine readable code, e.g. bar code
- 2201/09936 . . . Marks, inscriptions, etc. for information
- 2201/09945 . . . Universal aspects, e.g. universal inner layers or via grid, or anisotropic interposer
- 2201/09954 . . . More mounting possibilities, e.g. on same place of PCB, or by using different sets of edge pads
- 2201/09963 . . . Programming circuit by using small elements, e.g. small PCBs
- 2201/09972 . . . Partitioned, e.g. portions of a PCB dedicated to different functions; Boundary lines therefore; Portions of a PCB being processed separately or differently
- 2201/09981 . . . Metallised walls
- 2201/09985 . . . Hollow waveguide combined with printed circuit
- 2201/0999 . . . Circuit printed on or in housing, e.g. housing as PCB; Circuit printed on the case of a component; PCB affixed to housing
- 2201/10 . . Details of components or other objects attached to or integrated in a printed circuit board
- 2201/10007 . . Types of components
- 2201/10015 . . . Non-printed capacitor
- 2201/10022 . . . Non-printed resistor
- 2201/1003 . . . Non-printed inductor
- 2201/10037 . . . Printed or non-printed battery
- 2201/10045 . . . Mounted network component having plural terminals
- 2201/10053 . . . Switch
- 2201/1006 . . . Non-printed filter
- 2201/10068 . . . Non-printed resonator
- 2201/10075 . . . Non-printed oscillator
- 2201/10083 . . . Electromechanical or electro-acoustic component, e.g. microphone
- 2201/1009 . . . Electromotor
- 2201/10098 . . . Components for radio transmission, e.g. radio frequency identification [RFID] tag, printed or non-printed antennas
- 2201/10106 . . . Light emitting diode [LED]
- 2201/10113 . . . Lamp
- 2201/10121 . . . Optical component, e.g. opto-electronic component
- 2201/10128 . . . Display
- 2201/10136 Liquid Crystal display [LCD]
- 2201/10143 . . . Solar cell
- 2201/10151 . . . Sensor
- 2201/10159 . . . Memory
- 2201/10166 . . . Transistor
- 2201/10174 . . . Diode
- 2201/10181 . . . Fuse
- 2201/10189 . . . Non-printed connector
- 2201/10196 . . . Variable component, e.g. variable resistor
- 2201/10204 . . . Dummy component, dummy PCB or template, e.g. for monitoring, controlling of processes, comparing, scanning
- 2201/10212 . . . Programmable component
- 2201/10219 . . . Thermoelectric component
- 2201/10227 . . Other objects, e.g. metallic pieces
- 2201/10234 . . . Metallic balls
- 2201/10242 . . . Metallic cylinders
- 2201/1025 . . . Metallic discs
- 2201/10257 . . . Hollow pieces of metal, e.g. used in connection between component and PCB
- 2201/10265 . . . Metallic coils or springs, e.g. as part of a connection element
- 2201/10272 . . . Busbars, i.e. thick metal bars mounted on the printed circuit board [PCB] as high-current conductors
- 2201/1028 . . . Thin metal strips as connectors or conductors
- 2201/10287 . . . Metal wires as connectors or conductors
- 2201/10295 . . . Metallic connector elements partly mounted in a hole of the PCB
- 2201/10303 Pin-in-hole mounted pins
- 2201/1031 . . . Surface mounted metallic connector elements
- 2201/10318 Surface mounted metallic pins
- 2201/10325 . . . Sockets, i.e. female type connectors comprising metallic connector elements integrated in, or bonded to a common dielectric support
- 2201/10333 . . . Individual female type metallic connector elements
- 2201/1034 . . . Edge terminals, i.e. separate pieces of metal attached to the edge of the printed circuit board [PCB]
- 2201/10348 . . . Fuzz's as connector elements, i.e. small pieces of metallic fiber to make connection
- 2201/10356 . . . Cables
- 2201/10363 . . . Jumpers, i.e. non-printed cross-over connections
- 2201/10371 . . . Shields or metal cases
- 2201/10378 . . . Interposers
- 2201/10386 . . . Clip leads; Terminals gripping the edge of a substrate
- 2201/10393 . . . Clamping a component by an element or a set of elements
- 2201/10401 . . . Eyelets, i.e. rings inserted into a hole through a circuit board
- 2201/10409 . . . Screws
- 2201/10416 . . . Metallic blocks or heatsinks completely inserted in a PCB
- 2201/10424 . . . Frame holders
- 2201/10431 . . Details of mounted components
- 2201/10439 . . . Position of a single component
- 2201/10446 Mounted on an edge
- 2201/10454 Vertically mounted
- 2201/10462 Flat component oriented parallel to the PCB surface
- 2201/10469 Asymmetrically mounted component

- 2201/10477 Inverted
- 2201/10484 Obliquely mounted
- 2201/10492 Electrically connected to another device
- 2201/105 Mechanically attached to another device
- 2201/10507 Involving several components
- 2201/10515 Stacked components
- 2201/10522 Adjacent components
- 2201/1053 Mounted components directly electrically connected to each other, i.e. not via the PCB
- 2201/10537 Attached components
- 2201/10545 Related components mounted on both sides of the PCB
- 2201/10553 Component over metal, i.e. metal plate in between bottom of component and surface of PCB
- 2201/1056 Metal over component, i.e. metal plate over component mounted on or embedded in PCB
- 2201/10568 Integral adaptations of a component or an auxiliary PCB for mounting, e.g. integral spacer element
- 2201/10575 Insulating foil under component
- 2201/10583 Cylindrically shaped component; Fixing means therefore
- 2201/1059 Connections made by press-fit insertion
- 2201/10598 Means for fastening a component, a casing or a heat sink whereby a pressure is exerted on the component towards the PCB
- 2201/10606 Permanent holder for component or auxiliary printed circuits mounted on a printed circuit board [PCB]
- 2201/10613 Details of electrical connections of non-printed components, e.g. special leads
- 2201/10621 Components characterised by their electrical contacts
- 2201/10628 Leaded surface mounted device
- 2201/10636 Leadless chip, e.g. chip capacitor or resistor
- 2201/10643 Disc shaped leadless component
- 2201/10651 Component having two leads, e.g. resistor, capacitor
- 2201/10659 Different types of terminals for the same component, e.g. solder balls combined with leads
- 2201/10666 Plated through-hole for surface mounting on PCB
- 2201/10674 Flip chip
- 2201/10681 Tape Carrier Package [TCP]; Flexible sheet connector
- 2201/10689 Leaded Integrated Circuit [IC] package, e.g. dual-in-line [DIL]
- 2201/10696 Single-in-line [SIL] package
- 2201/10704 Pin grid array [PGA]
- 2201/10712 Via grid array, e.g. via grid array capacitor
- 2201/10719 Land grid array [LGA]
- 2201/10727 Leadless chip carrier [LCC], e.g. chip-modules for cards
- 2201/10734 Ball grid array [BGA]; Bump grid array
- 2201/10742 Details of leads
- 2201/1075 Shape details
- 2201/10757 Bent leads
- 2201/10765 Leads folded back, i.e. bent with an angle of 180 deg
- 2201/10772 Leads of a surface mounted component bent for providing a gap between the lead and the pad during soldering
- 2201/1078 Leads having locally deformed portion, e.g. for retention
- 2201/10787 Leads having protrusions, e.g. for retention or insert stop
- 2201/10795 Details of lead tips, e.g. pointed
- 2201/10803 Tapered leads, i.e. leads having changing width or diameter
- 2201/1081 Special cross-section of a lead; Different cross-sections of different leads; Matching cross-section, e.g. matched to a land
- 2201/10818 Flat leads
- 2201/10825 Distorted or twisted flat leads, i.e. deformed by torque
- 2201/10833 having a curved or folded cross-section
- 2201/1084 Notched leads
- 2201/10848 Thinned leads
- 2201/10856 Divided leads, e.g. by slot in length direction of lead, or by branching of the lead
- 2201/10863 Adaptations of leads or holes for facilitating insertion
- 2201/10871 Leads having an integral insert stop
- 2201/10878 Means for retention of a lead in a hole
- 2201/10886 Other details
- 2201/10893 Grouped leads, i.e. element comprising multiple leads distributed around but not through a common insulator
- 2201/10901 Lead partly inserted in hole or via
- 2201/10909 Materials of terminal, e.g. of leads or electrodes of components
- 2201/10916 Terminals having auxiliary metallic piece, e.g. for soldering
- 2201/10924 Leads formed from a punched metal foil
- 2201/10931 Exposed leads, i.e. encapsulation of component partly removed for exposing a part of lead, e.g. for soldering purposes
- 2201/10939 Lead of component used as a connector
- 2201/10946 Leads attached onto leadless component after manufacturing the component
- 2201/10954 Other details of electrical connections
- 2201/10962 Component not directly connected to the PCB
- 2201/10969 Metallic case or integral heatsink of component electrically connected to a pad on PCB
- 2201/10977 Encapsulated connections
- 2201/10984 Component carrying a connection agent, e.g. solder, adhesive
- 2201/10992 Using different connection materials, e.g. different solders, for the same connection
- 2201/20 Details of printed circuits not provided for in [H05K 2201/01](#) - [H05K 2201/10](#)
- 2201/2009 Reinforced areas, e.g. for a specific part of a flexible printed circuit
- 2201/2018 Presence of a frame in a printed circuit or printed circuit assembly
- 2201/2027 Guiding means, e.g. for guiding flexible circuits
- 2201/2036 Permanent spacer or stand-off in a printed circuit or printed circuit assembly
- 2201/2045 Protection against vibrations

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- 2201/2054 . . Light-reflecting surface, e.g. conductors, substrates, coatings, dielectrics
- 2201/2063 . . mixed adhesion layer containing metallic/inorganic and polymeric materials
- 2201/2072 . . Anchoring, i.e. one structure gripping into another
- 2201/2081 . . Compound repelling a metal, e.g. solder
- 2201/209 . . Auto-mechanical connection between a component and a PCB or between two PCBs
- 2203/00** **Indexing scheme relating to apparatus or processes for manufacturing printed circuits covered by [H05K 3/00](#)**
- 2203/01 . Tools for processing; Objects used during processing
- 2203/0104 . . for patterning or coating
- 2203/0108 . . . Male die used for patterning, punching or transferring
- 2203/0113 . . . Female die used for patterning or transferring, e.g. temporary substrate having recessed pattern
- 2203/0117 . . . Pattern shaped electrode used for patterning, e.g. plating or etching
- 2203/0121 . . . Patterning, e.g. plating or etching by moving electrode
- 2203/0126 . . . Dispenser, e.g. for solder paste, for supplying conductive paste for screen printing or for filling holes
- 2203/013 . . . Inkjet printing, e.g. for printing insulating material or resist
- 2203/0134 . . . Drum, e.g. rotary drum or dispenser with a plurality of openings
- 2203/0139 . . . Blade or squeegee, e.g. for screen printing or filling of holes
- 2203/0143 . . . Using a roller; Specific shape thereof; Providing locally adhesive portions thereon
- 2203/0147 . . Carriers and holders
- 2203/0152 . . . Temporary metallic carrier, e.g. for transferring material
- 2203/0156 . . . Temporary polymeric carrier or foil, e.g. for processing or transferring
- 2203/016 . . . Temporary inorganic, non-metallic carrier, e.g. for processing or transferring
- 2203/0165 . . . Holder for holding a Printed Circuit Board [PCB] during processing, e.g. during screen printing
- 2203/0169 . . . Using a temporary frame during processing
- 2203/0173 . . . Template for holding a PCB having mounted components thereon
- 2203/0178 . . Projectile, e.g. for perforating substrate
- 2203/0182 . . Using a temporary spacer element or stand-off during processing
- 2203/0186 . . Mask formed or laid on PCB, the mask having recesses or openings specially designed for mounting components or body parts thereof
- 2203/0191 . . Using tape or non-metallic foil in a process, e.g. during filling of a hole with conductive paste
- 2203/0195 . . Tool for a process not provided for in [H05K 3/00](#), e.g. tool for handling objects using suction, for deforming objects, for applying local pressure
- 2203/02 . Details related to mechanical or acoustic processing, e.g. drilling, punching, cutting, using ultrasound
- 2203/0207 . . Partly drilling through substrate until a controlled depth, e.g. with end-point detection
- 2203/0214 . . Back-up or entry material, e.g. for mechanical drilling
- 2203/0221 . . Perforating
- 2203/0228 . . Cutting, sawing, milling or shearing
- 2203/0235 . . Laminating followed by cutting or slicing perpendicular to plane of the laminate; Embedding wires in an object and cutting or slicing the object perpendicular to direction of the wires
- 2203/0242 . . Cutting around hole, e.g. for disconnecting land or Plated Through-Hole [PTH] or for partly removing a PTH
- 2203/025 . . Abrading, e.g. grinding or sand blasting
- 2203/0257 . . Brushing, e.g. cleaning the conductive pattern by brushing or wiping
- 2203/0264 . . Peeling insulating layer, e.g. foil, or separating mask
- 2203/0271 . . Mechanical force other than pressure, e.g. shearing or pulling
- 2203/0278 . . Flat pressure, e.g. for connecting terminals with anisotropic conductive adhesive
- 2203/0285 . . Using ultrasound, e.g. for cleaning, soldering or wet treatment
- 2203/0292 . . Using vibration, e.g. during soldering or screen printing
- 2203/03 . Metal processing
- 2203/0307 . . Providing micro- or nanometer scale roughness on a metal surface, e.g. by plating of nodules or dendrites
- 2203/0315 . . Oxidising metal
- 2203/0323 . . Working metal substrate or core, e.g. by etching, deforming
- 2203/033 . . Punching metal foil, e.g. solder foil
- 2203/0338 . . Transferring metal or conductive material other than a circuit pattern, e.g. bump, solder, printed component
- 2203/0346 . . Deburring, rounding, bevelling or smoothing conductor edges
- 2203/0353 . . Making conductive layer thin, e.g. by etching
- 2203/0361 . . Stripping a part of an upper metal layer to expose a lower metal layer, e.g. by etching or using a laser
- 2203/0369 . . Etching selective parts of a metal substrate through part of its thickness, e.g. using etch resist
- 2203/0376 . . Etching temporary metallic carrier substrate
- 2203/0384 . . Etch stop layer, i.e. a buried barrier layer for preventing etching of layers under the etch stop layer
- 2203/0392 . . Pretreatment of metal, e.g. before finish plating, etching
- 2203/04 . Soldering or other types of metallurgic bonding
- 2203/0405 . . Solder foil, tape or wire
- 2203/041 . . Solder preforms in the shape of solder balls
- 2203/0415 . . Small preforms other than balls, e.g. discs, cylinders or pillars
- 2203/042 . . Remote solder depot on the PCB, the solder flowing to the connections from this depot
- 2203/0425 . . Solder powder or solder coated metal powder
- 2203/043 . . Reflowing of solder coated conductors, not during connection of components, e.g. reflowing solder paste
- 2203/0435 . . Metal coated solder, e.g. for passivation of solder balls

- 2203/044 . . Solder dip coating, i.e. coating printed conductors, e.g. pads by dipping in molten solder or by wave soldering
- 2203/0445 . . Removing excess solder on pads; removing solder bridges, e.g. for repairing or reworking
- 2203/045 . . Solder-filled plated through-hole [PTH] during processing wherein the solder is removed from the PTH after processing
- 2203/0455 . . PTH for surface mount device [SMD], e.g. wherein solder flows through the PTH during mounting
- 2203/046 . . Means for drawing solder, e.g. for removing excess solder from pads
- 2203/0465 . . Shape of solder, e.g. differing from spherical shape, different shapes due to different solder pads
- 2203/047 . . Soldering with different solders, e.g. two different solders on two sides of the PCB
- 2203/0475 . . Molten solder just before placing the component
- 2203/048 . . Self-alignment during soldering; Terminals, pads or shape of solder adapted therefor
- 2203/0485 . . Tacky flux, e.g. for adhering components during mounting
- 2203/049 . . Wire bonding
- 2203/0495 . . Cold welding
- 2203/05 . . Patterning and lithography; Masks; Details of resist
- 2203/0502 . . Patterning and lithography
- 2203/0505 . . . Double exposure of the same photosensitive layer
- 2203/0508 . . . Flood exposure
- 2203/0511 . . . Diffusion patterning
- 2203/0514 . . . Photodevelopable thick film, e.g. conductive or insulating paste
- 2203/0517 . . . Electrographic patterning
- 2203/052 . . . Magnetographic patterning
- 2203/0522 . . . Using an adhesive pattern
- 2203/0525 . . . Patterning by phototackifying or by photopatterning adhesive
- 2203/0528 . . . Patterning during transfer, i.e. without preformed pattern, e.g. by using a die, a programmed tool or a laser
- 2203/0531 . . . Decalomania, i.e. transfer of a pattern detached from its carrier before affixing the pattern to the substrate
- 2203/0534 . . . Offset printing, i.e. transfer of a pattern from a carrier onto the substrate by using an intermediate member
- 2203/0537 . . . Transfer of pre-fabricated insulating pattern
- 2203/054 . . . Continuous temporary metal layer over resist, e.g. for selective electroplating
- 2203/0542 . . . Continuous temporary metal layer over metal pattern
- 2203/0545 . . . Pattern for applying drops or paste; Applying a pattern made of drops or paste
- 2203/0548 . . Masks
- 2203/0551 . . . Exposure mask directly printed on the PCB
- 2203/0554 . . . Metal used as mask for etching vias, e.g. by laser ablation
- 2203/0557 . . . Non-printed masks
- 2203/056 . . . Using an artwork, i.e. a photomask for exposing photosensitive layers
- 2203/0562 . . Details of resist
- 2203/0565 . . . Resist used only for applying catalyst, not for plating itself
- 2203/0568 . . . Resist used for applying paste, ink or powder
- 2203/0571 . . . Dual purpose resist, e.g. etch resist used as solder resist, solder resist used as plating resist
- 2203/0574 . . . Stacked resist layers used for different processes
- 2203/0577 . . . Double layer of resist having the same pattern
- 2203/058 . . . Additional resists used for the same purpose but in different areas, i.e. not stacked
- 2203/0582 . . . Coating by resist, i.e. resist used as mask for application of insulating coating or of second resist
- 2203/0585 . . . Second resist used as mask for selective stripping of first resist
- 2203/0588 . . . Second resist used as pattern over first resist
- 2203/0591 . . . Organic non-polymeric coating, e.g. for inhibiting corrosion thereby preserving solderability
- 2203/0594 . . . Insulating resist or coating with special shaped edges
- 2203/0597 . . . Resist applied over the edges or sides of conductors, e.g. for protection during etching or plating
- 2203/06 . . Lamination
- 2203/061 . . of previously made multilayered subassemblies
- 2203/063 . . of preperforated insulating layer
- 2203/065 . . Binding insulating layers without adhesive, e.g. by local heating or welding, before lamination of the whole PCB
- 2203/066 . . Transfer laminating of insulating material, e.g. resist as a whole layer, not as a pattern
- 2203/068 . . Features of the lamination press or of the lamination process, e.g. using special separator sheets
- 2203/07 . . Treatments involving liquids, e.g. plating, rinsing
- 2203/0703 . . Plating
- 2203/0706 . . . Inactivating or removing catalyst, e.g. on surface of resist
- 2203/0709 . . . Catalytic ink or adhesive for electroless plating
- 2203/0713 . . . Plating poison, e.g. for selective plating or for preventing plating on resist
- 2203/0716 . . . Metallic plating catalysts, e.g. for direct electroplating of through holes; Sensitising or activating metallic plating catalysts
- 2203/072 . . . Electroless plating, e.g. finish plating or initial plating
- 2203/0723 . . . Electroplating, e.g. finish plating
- 2203/0726 . . . Electroforming, i.e. electroplating on a metallic carrier thereby forming a self-supporting structure
- 2203/073 . . . Displacement plating, substitution plating or immersion plating, e.g. for finish plating
- 2203/0733 . . . Method for plating stud vias, i.e. massive vias formed by plating the bottom of a hole without plating on the walls
- 2203/0736 . . Methods for applying liquids, e.g. spraying
- 2203/074 . . . Features related to the fluid pressure
- 2203/0743 . . . Mechanical agitation of fluid, e.g. during cleaning of the conductive pattern
- 2203/0746 . . . Local treatment using a fluid jet, e.g. for removing or cleaning material; Providing mechanical pressure using a fluid jet
- 2203/075 . . . Global treatment of printed circuits by fluid spraying, e.g. cleaning a conductive pattern using nozzles

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- 2203/0753 . . . Reversing fluid direction, e.g. in holes
- 2203/0756 . . Uses of liquids, e.g. rinsing, coating, dissolving
- 2203/0759 . . . Forming a polymer layer by liquid coating, e.g. a non-metallic protective coating or an organic bonding layer
- 2203/0763 . . . Treating individual holes or single row of holes, e.g. by nozzle
- 2203/0766 . . . Rinsing, e.g. after cleaning or polishing a conductive pattern
- 2203/0769 . . . Dissolving insulating materials, e.g. coatings, not used for developing resist after exposure
- 2203/0773 . . . Dissolving the filler without dissolving the matrix material; Dissolving the matrix material without dissolving the filler
- 2203/0776 . . . Uses of liquids not otherwise provided for in [H05K 2203/0759](#) - [H05K 2203/0773](#)
- 2203/0779 . . characterised by the specific liquids involved
- 2203/0783 . . . Using solvent, e.g. for cleaning; Regulating solvent content of pastes or coatings for adjusting the viscosity
- 2203/0786 . . . Using an aqueous solution, e.g. for cleaning or during drilling of holes
- 2203/0789 Aqueous acid solution, e.g. for cleaning or etching
- 2203/0793 Aqueous alkaline solution, e.g. for cleaning or etching
- 2203/0796 Oxidant in aqueous solution, e.g. permanganate
- 2203/08 . Treatments involving gases
- 2203/081 . . Blowing of gas, e.g. for cooling or for providing heat during solder reflowing
- 2203/082 . . Suction, e.g. for holding solder balls or components
- 2203/083 . . Evaporation or sublimation of a compound, e.g. gas bubble generating agent
- 2203/085 . . Using vacuum or low pressure
- 2203/086 . . Using an inert gas
- 2203/087 . . Using a reactive gas
- 2203/088 . . Using a vapour or mist, e.g. cleaning using water vapor
- 2203/09 . Treatments involving charged particles
- 2203/092 . . Particle beam, e.g. using an electron beam or an ion beam
- 2203/095 . . Plasma, e.g. for treating a substrate to improve adhesion with a conductor or for cleaning holes
- 2203/097 . . . Corona discharge
- 2203/10 . Using electric, magnetic and electromagnetic fields; Using laser light
- 2203/101 . . Using electrical induction, e.g. for heating during soldering
- 2203/102 . . Using microwaves, e.g. for curing ink patterns or adhesive
- 2203/104 . . Using magnetic force, e.g. to align particles or for a temporary connection during processing
- 2203/105 . . Using an electrical field; Special methods of applying an electric potential
- 2203/107 . . Using laser light
- 2203/108 . . . Using a plurality of lasers or laser light with a plurality of wavelengths
- 2203/11 . Treatments characterised by their effect, e.g. heating, cooling, roughening
- 2203/1105 . . Heating or thermal processing not related to soldering, firing, curing or laminating, e.g. for shaping the substrate or during finish plating
- 2203/111 . . Preheating, e.g. before soldering
- 2203/1115 . . Resistance heating, e.g. by current through the PCB conductors or through a metallic mask
- 2203/1121 . . Cooling, e.g. specific areas of a PCB being cooled during reflow soldering
- 2203/1126 . . Firing, i.e. heating a powder or paste above the melting temperature of at least one of its constituents
- 2203/1131 . . Sintering, i.e. fusing of metal particles to achieve or improve electrical conductivity
- 2203/1136 . . Conversion of insulating material into conductive material, e.g. by pyrolysis
- 2203/1142 . . Conversion of conductive material into insulating material or into dissolvable compound
- 2203/1147 . . Sealing or impregnating, e.g. of pores
- 2203/1152 . . Replicating the surface structure of a sacrificial layer, e.g. for roughening
- 2203/1157 . . Using means for chemical reduction
- 2203/1163 . . Chemical reaction, e.g. heating solder by exothermic reaction
- 2203/1168 . . Graft-polymerization
- 2203/1173 . . Differences in wettability, e.g. hydrophilic or hydrophobic areas
- 2203/1178 . . Means for venting or for letting gases escape
- 2203/1184 . . Underetching, e.g. etching of substrate under conductors or etching of conductor under dielectrics; Means for allowing or controlling underetching
- 2203/1189 . . Pressing leads, bumps or a die through an insulating layer
- 2203/1194 . . Thermal treatment leading to a different chemical state of a material, e.g. annealing for stress-relief, aging
- 2203/12 . Using specific substances
- 2203/121 . . Metallo-organic compounds
- 2203/122 . . Organic non-polymeric compounds, e.g. oil, wax or thiol
- 2203/124 . . . Heterocyclic organic compounds, e.g. azole, furan
- 2203/125 . . Inorganic compounds, e.g. silver salt
- 2203/127 . . Lubricants, e.g. during drilling of holes
- 2203/128 . . Molten metals, e.g. casting thereof, or melting by heating and excluding molten solder
- 2203/13 . Moulding and encapsulation; Deposition techniques; Protective layers
- 2203/1305 . . Moulding and encapsulation
- 2203/1311 . . . Foil encapsulation, e.g. of mounted components
- 2203/1316 . . . Moulded encapsulation of mounted components
- 2203/1322 . . . Encapsulation comprising more than one layer
- 2203/1327 . . . Moulding over PCB locally or completely
- 2203/1333 . . Deposition techniques, e.g. coating
- 2203/1338 . . . Chemical vapour deposition
- 2203/1344 . . . Spraying small metal particles or droplets of molten metal
- 2203/135 . . . Electrophoretic deposition of insulating material
- 2203/1355 . . . Powder coating of insulating material
- 2203/1361 . . . Coating by immersion in coating bath
- 2203/1366 . . . Spraying coating
- 2203/1372 . . . Coating by using a liquid wave
- 2203/1377 . . Protective layers

- 2203/1383 . . . Temporary protective insulating layer
- 2203/1388 . . . Temporary protective conductive layer
- 2203/1394 . . . Covering open PTHs, e.g. by dry film resist or by metal disc
- 2203/14 . . . Related to the order of processing steps
- 2203/1407 . . . Applying catalyst before applying plating resist
- 2203/1415 . . . Applying catalyst after applying plating resist
- 2203/1423 . . . Applying catalyst before etching, e.g. plating catalyst in holes before etching circuit
- 2203/143 . . . Treating holes before another process, e.g. coating holes before coating the substrate
- 2203/1438 . . . Treating holes after another process, e.g. coating holes after coating the substrate
- 2203/1446 . . . Treatment after insertion of lead into hole, e.g. bending, cutting, caulking or curing of adhesive but excluding soldering
- 2203/1453 . . . Applying the circuit pattern before another process, e.g. before filling of vias with conductive paste, before making printed resistors
- 2203/1461 . . . Applying or finishing the circuit pattern after another process, e.g. after filling of vias with conductive paste, after making printed resistors
- 2203/1469 . . . Circuit made after mounting or encapsulation of the components
- 2203/1476 . . . Same or similar kind of process performed in phases, e.g. coarse patterning followed by fine patterning
- 2203/1484 . . . Simultaneous treatments, e.g. soldering lead-in-hole components simultaneously with surface mounted components
- 2203/1492 . . . Periodical treatments, e.g. pulse plating of through-holes
- 2203/15 . . . Position of the PCB during processing
- 2203/1509 . . . Horizontally held PCB
- 2203/1518 . . . Vertically held PCB
- 2203/1527 . . . Obliquely held PCB
- 2203/1536 . . . Temporarily stacked PCBs
- 2203/1545 . . . Continuous processing, i.e. involving rolls moving a band-like or solid carrier along a continuous production path
- 2203/1554 . . . Rotating or turning the PCB in a continuous manner
- 2203/1563 . . . Reversing the PCB
- 2203/1572 . . . Processing both sides of a PCB by the same process; Providing a similar arrangement of components on both sides; Making interlayer connections from two sides
- 2203/1581 . . . Treating the backside of the PCB, e.g. for heating during soldering or providing a liquid coating on the backside
- 2203/159 . . . Using gravitational force; Processing against the gravity direction; Using centrifugal force
- 2203/16 . . . Inspection; Monitoring; Aligning
- 2203/161 . . . Using chemical substances, e.g. colored or fluorescent, for facilitating optical or visual inspection
- 2203/162 . . . Testing a finished product, e.g. heat cycle testing of solder joints
- 2203/163 . . . Monitoring a manufacturing process
- 2203/165 . . . Stabilizing, e.g. temperature stabilization
- 2203/166 . . . Alignment or registration; Control of registration
- 2203/167 . . . Using mechanical means for positioning, alignment or registration, e.g. using rod-in-hole alignment
- 2203/168 . . . Wrong mounting prevention
- 2203/17 . . . Post-manufacturing processes
- 2203/171 . . . Tuning, e.g. by trimming of printed components or high frequency circuits
- 2203/173 . . . Adding connections between adjacent pads or conductors, e.g. for modifying or repairing
- 2203/175 . . . Configurations of connections suitable for easy deletion, e.g. modifiable circuits or temporary conductors for electroplating; Processes for deleting connections
- 2203/176 . . . Removing, replacing or disconnecting component; Easily removable component
- 2203/178 . . . Demolishing, e.g. recycling, reverse engineering, destroying for security purposes; Using biodegradable materials
- 2203/30 . . . Details of processes not otherwise provided for in [H05K 2203/01](#) - [H05K 2203/17](#)
- 2203/302 . . . Bending a rigid substrate; Breaking rigid substrates by bending
- 2203/304 . . . Protecting a component during manufacturing
- 2203/306 . . . Lifting the component during or after mounting; Increasing the gap between component and PCB
- 2203/308 . . . Sacrificial means, e.g. for temporarily filling a space for making a via or a cavity or for making rigid-flexible PCBs